

# Notice for TAIYO YUDEN Products

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Please read this notice before using the TAIYO YUDEN products.



## REMINDERS

### ■ Product Information in this Catalog

Product information in this catalog is as of October 2021. All of the contents specified herein and production status of the products listed in this catalog are subject to change without notice due to technical improvement of our products, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

### ■ Approval of Product Specifications

Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available. When using our products, please be sure to approve our product specifications or make a written agreement on the product specification with TAIYO YUDEN in advance.

### ■ Pre-Evaluation in the Actual Equipment and Conditions

Please conduct validation and verification of our products in actual conditions of mounting and operating environment before using our products.

### ■ Safety Design

When using our products for high safety and/or reliability-required equipment or circuits, please fully perform safety and/or reliability evaluation. In addition, please install (i) systems equipped with a protection circuit and a protection device and/or (ii) systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault for a failsafe design to ensure safety.

### ■ Intellectual Property Rights

Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.

### ■ Limited Warranty

Please note that the scope of warranty for our products is limited to the delivered our products themselves conforming to the product specifications specified in the individual product specification sheets, and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a failure or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement, provided, however, that our products shall be used for general-purpose and standard use in the equipment specified in this catalog or the individual product specification sheets.

### ■ TAIYO YUDEN's Official Sales Channel

The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

### ■ Caution for Export

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

## ■ Limited Application

### 1. Equipment Intended for Use

The products listed in this catalog are intended for general-purpose and standard use in general electronic equipment for consumer (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC) and other equipment specified in this catalog or the individual product specification sheets, or the equipment approved separately by TAIYO YUDEN.

TAIYO YUDEN has the product series intended for use in the following equipment. Therefore, when using our products for these equipment, please check available applications specified in this catalog or the individual product specification sheets and use the corresponding products.

Application	Product Series		Quality Grade <sup>*3</sup>
	Equipment <sup>*1</sup>	Category (Part Number Code <sup>*2</sup> )	
Automotive	Automotive Electronic Equipment (POWERTRAIN, SAFETY)	A	1
	Automotive Electronic Equipment (BODY & CHASSIS, INFOTAINMENT)	C	2
Industrial	Telecommunications Infrastructure and Industrial Equipment	B	2
Medical	Medical Devices classified as GHTF Class C (Japan Class III)	M	2
	Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)	L	3
Consumer	General Electronic Equipment	S	3

\*Notes: 1. Based on the general specifications required for electronic components for such equipment, which are recognized by TAIYO YUDEN, the use of each product series for the equipment is recommended. Please be sure to contact TAIYO YUDEN before using our products for equipment other than those covered by the product series.

2. On each of our part number, the 2nd code from the left is a code indicating the "Category" as shown in the above table. For details, please check the explanatory materials regarding the part numbering system of each of our products.

3. Each product series is assigned a "Quality Grade" from 1 to 3 in order of higher quality. Please do not incorporate a product into any equipment with a higher Quality Grade than the Quality Grade of such product without the prior written consent of TAIYO YUDEN.

### 2. Equipment Requiring Inquiry

Please be sure to contact TAIYO YUDEN for further information before using the products listed in this catalog for the following equipment (excluding intended equipment as specified in this catalog or the individual product specification sheets) which may cause loss of human life, bodily injury, serious property damage and/or serious public impact due to a failure or defect of the products and/or malfunction attributed thereto.

- (1) Transportation equipment (automotive powertrain control system, train control system, and ship control system, etc.)
- (2) Traffic signal equipment
- (3) Disaster prevention equipment, crime prevention equipment
- (4) Medical devices classified as GHTF Class C (Japan Class III)
- (5) Highly public information network equipment, data-processing equipment (telephone exchange, and base station, etc.)
- (6) Any other equipment requiring high levels of quality and/or reliability equal to the equipment listed above

### 3. Equipment Prohibited for Use

Please do not incorporate our products into the following equipment requiring extremely high levels of safety and/or reliability.

- (1) Aerospace equipment (artificial satellite, rocket, etc.)
- (2) Aviation equipment <sup>\*1</sup>
- (3) Medical devices classified as GHTF Class D (Japan Class IV), implantable medical devices <sup>\*2</sup>
- (4) Power generation control equipment (nuclear power, hydroelectric power, thermal power plant control system, etc.)
- (5) Undersea equipment (submarine repeating equipment, etc.)
- (6) Military equipment
- (7) Any other equipment requiring extremely high levels of safety and/or reliability equal to the equipment listed above

\*Notes: 1. There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.

2. Implantable medical devices contain not only internal unit which is implanted in a body, but also external unit which is connected to the internal unit.


### 4. Limitation of Liability

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment that is not intended for use by TAIYO YUDEN, or any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

# Medical Application Guide

According to the medical devices classified as GHTF Classes A to C (Japan Classes I to III), we have the corresponding product series (the part number code of 2nd digit from the left side is "M" or "L") intended for use in the medical devices. Therefore, when using our products for the medical devices, please be sure to check the classification based on the GHTF Rules and use the corresponding product series.

On the other hand, we don't have the product series intended for use in (i) all medical devices classified as GHTF Class D (Japan Class IV) and (ii) implantable medical devices (bone-anchored hearing aid, artificial retina system, and external unit which is connected to internal unit which is implanted in a body, etc.). Therefore, please do not incorporate our products into these medical devices. Should you have any questions on this matter, please contact us.

Risk Level		Low  High			
Japan	Classification according to the PMD Act of Japan (based on the GHTF Rules)	<b>Class I</b> General Medical Devices (GHTF Class A)	<b>Class II</b> Controlled Medical Devices (GHTF Class B)	<b>Class III</b> Specially-controlled Medical Devices (GHTF Class C)	<b>Class IV</b> Specially-controlled Medical Devices (GHTF Class D)
		Medical devices with extremely low risk to the human body in case of problems  [Ex.] • In Vitro Diagnostic Devices • Nebulizer • Blood Gas Analyzer • Plethysmographs • Breathing Sensor • AC-powered Operating Table • Surgical Light • Cholesterol Analysis Device • Blood Type Analysis Device, etc.	Medical devices with relatively low risk to the human body in case of problems  [Ex.] • Electronic Thermometer • Electronic Blood Pressure Gauge • Electronic Endoscope • Hearing Aid • Electrocardiograph • MRI • Ultrasonic Diagnostic System • Diagnostic Imaging Equipment • X-ray Diagnostic Equipment • Central Monitor • Pulse Oximeter, etc.	Medical devices with relatively high risk to the human body in case of problems  [Ex.] • Dialysis Machine • Radiation Therapy Equipment • Infusion Pump • Respirator • Glucose Monitoring System • AED (Automated External Defibrillator) • Skin Laser Scanner • Electric Surgical Unit • Insulin Pump, etc.	Medical devices highly invasive to patients and with life-threatening risk in case of problems  [Ex.] • Cardiac Pacemaker • Video Flexible Angioscope • Implantable Infusion Pump • Cardiac Electrosurgical Unit • Inspection Device with Cardiac Catheter • Defibrillator, etc.
U.S.A.	FDA Classification	<b>Class I</b> General Controls	<b>Class II</b> General Controls and Special Controls	<b>Class III</b> General Controls and Premarket Approval	
		Medical devices without the possibility of causing serious injury or harm to the patient or user even if there is a defect or malfunction in such medical devices	Medical devices with the possibility of causing injury or harm to the patient or user if there is a defect or malfunction in such medical devices	Medical devices with the possibility of causing serious injury, disability or death to the patient or user if a defect or malfunction occurs in such medical devices	
Corresponding TAIYO YUDEN Product Series	<b>Product Series for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)</b> (Part Number Code of 2nd Digit from the Left Side: "L")		<b>Product Series for Medical Devices classified as GHTF Class C (Japan Class III)</b> (Part Number Code of 2nd Digit from the Left Side: "M") (See the Note below.)		N / A

\* Note : It is prohibited that our products are used in some medical devices such as implantable medical devices even if such medical

# Multilayer Ceramic Capacitors

## for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)

REFLOW

## PART NUMBER

M	L	A	S	U	3	1	L	B	B	5	1	0	6	K	T	N	A	0	1
①	②	③	④	⑤	⑥	⑦	⑧	⑨	⑩										

## ① Series

Code (1)(2)(3)(4)	
MLAS	Multilayer Ceramic Capacitor (High dielectric type) for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II) Multilayer Ceramic Capacitor (Temperature compensating type) for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II) Medium-High Voltage Multilayer Ceramic Capacitor for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)
MLAY	Low distortion design/Audible/Good bias Multilayer Ceramic Capacitor for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)
MLRL	LW Reversal Decoupling Low ESL Capacitor(LWDC™) for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)

## (1) Product Group

Code	
M	Multilayer Ceramic Capacitor

## (2) Category

Code	Recommended equipment	Quality Grade
L	Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)	3

## (3) Type

Code	
A	2 terminals
R	LW reversal

## (4) Features, Characteristics

Code	
S	Standard/General
Y	Low distortion design/Audible/Good bias
L	Low ESL

## ② Rated voltage

Code	Rated voltage [VDC]
P	2.5
A	4
J	6.3
L	10
E	16
T	25
G	35
U	50
H	100
Q	250
S	630
X	2000

## ④ Thickness

Code	Thickness [mm]
H	0.13 (1.5 max ※)
E	0.18 (1.1 max ※)
2	0.2
3	0.3
K	0.45
5	0.5
8	0.8
9	0.85
Q	1.15
G	1.25
L	1.6
N	1.9 (0.088 ※)
Y	2.0 max
M	2.5

Note : ※LW reverse type (MLRL)

## ③ Dimension

Code	(L × W) [mm]	JIS(mm)	EIA(inch)
04	0.4 × 0.2	0402	01005
06	0.6 × 0.3	0603	0201
1L	1.0 × 0.5	1005	0402
10	1.0 × 0.5	1005	0402
	0.52 × 1.0 ※	0510	0204
16	1.6 × 0.8	1608	0603
	0.8 × 1.6 ※	0816	0306
21	2.0 × 1.25	2012	0805
	1.25 × 2.0 ※	1220	0508
31	3.2 × 1.6	3216	1206
32	3.2 × 2.5	3225	1210
45	4.5 × 3.2	4532	1812

Note : ※LW reverse type (MLRL)

## ⑤Dimension tolerance

Code	Dimension code	L[mm]	W[mm]	T[mm]	Thickness code
A	06	0.6±0.05	0.3±0.05	0.3±0.05	3
	10	1.0±0.10	0.5±0.10	0.5±0.10	5
	16	1.6+0.15/-0.05	0.8+0.15/-0.05	0.8+0.15/-0.05	8
	21	2.0+0.15/-0.05	1.25+0.15/-0.05	1.25+0.15/-0.05	G
	31	3.2±0.20	1.6±0.20	1.6±0.20	L
	32	3.2±0.30	2.5±0.30	2.5±0.30	M
	45	4.5±0.40	3.2±0.30	2.0+0/-0.30	Y
B	06	0.6±0.09	0.3±0.09	0.3±0.09	3
	10	1.0+0.15/-0.05	0.5+0.15/-0.05	0.5+0.15/-0.05	5
	16	1.6+0.20/-0	0.8+0.20/-0	0.8+0.20/-0	8
	21	2.0+0.20/-0	1.25+0.20/-0	1.25+0.20/-0	G
	31	3.2±0.30	1.6±0.30	1.6±0.30	L
	32	3.2±0.30	2.5±0.20	1.9+0.1/-0.20	Y
C	10	1.0+0.20/-0	0.5+0.20/-0	0.5+0.20/-0	5
E	06	0.6+0.25/-0	0.3+0.25/-0	0.3+0.25/-0	3
H	31	3.2±0.15	1.6±0.15	0.85±0.10	9
				1.15±0.10	Q
J	16	1.6+0.20/-0	0.8+0.20/-0	0.45±0.05	K
	21	2.0+0.15/-0.05	1.25+0.15/-0.05	0.85±0.10	9
	32	3.2±0.30	2.5±0.20	0.85±0.10	9
				1.15±0.10	Q
L	21	2.0+0.20/-0	1.25+0.20/-0	0.85±0.10	9
	31	3.2±0.20	1.6±0.20	0.85±0.10	9
S	04	0.4±0.02	0.2±0.02	0.2±0.02	2
	06	0.6±0.03	0.3±0.03	0.3±0.03	3
		1.0±0.05	0.5±0.05	0.5±0.05	5
	10	0.52±0.05 ※	1.0±0.05	0.3±0.05	3
		1.6±0.10	0.8±0.10	0.8±0.10	8
	16	0.8±0.10 ※	1.6±0.10	0.5±0.05	5
		2.0±0.10	1.25±0.10	0.85±0.10	9
	21	1.25±0.15 ※	2.0±0.15	1.25±0.10	G
		0.85±0.10	2.0±0.15	0.85±0.10	9
	31	3.2±0.15	1.6±0.15	1.6±0.20	L
32	3.2±0.30	2.5±0.20	2.5±0.20	M	
	1.9±0.20			N	
45	4.5±0.40	3.2±0.30	2.5±0.20	M	
T	16	1.6±0.10	0.8±0.10	0.45±0.05	K
X	1L	1.0±0.05	0.5±0.05	0.13±0.02	H
				0.18±0.02	E
				0.2±0.02	2
Y	1L	1.0±0.05	0.5±0.05	0.3±0.03	3

Note :※LW reverse type (MLRL)

⑥ Temperature characteristics code

■ High dielectric type (SD: Excluding Low distortion design/Audible/Good bias Multilayer Ceramic Capacitor)

Code	Applicable standard		Temperature range [°C]	Ref. Temp. [°C]	Capacitance change	Capacitance tolerance	Tolerance code
B5	JIS	B	-25 ~ + 85	20	± 10%	± 10%	K
						± 20%	M
	EIA	X5R	-55 ~ + 85	25	± 15%	± 10%	K
						± 20%	M
B7	EIA	X7R	-55 ~ + 125	25	± 15%	± 10%	K
						± 20%	M
C6	EIA	X6S	-55 ~ + 105	25	± 22%	± 10%	K
						± 20%	M
C7	EIA	X7S	-55 ~ + 125	25	± 22%	± 10%	K
						± 20%	M
LD(※)	EIA	X5R	-55 ~ + 85	25	± 15%	± 10%	K
						± 20%	M

Note : ※.LD: Low distortion design/Audible/Good bias Multilayer Ceramic Capacitor

■ Temperature compensating type

Code	Applicable standard		Temperature range [°C]	Ref. Temp. [°C]	Capacitance change	Capacitance tolerance	Tolerance code		
CG	JIS	CG	-55 ~ + 125	20	0 ± 30ppm/°C	± 0.05pF	A		
						± 0.1pF	B		
	± 0.25pF	C							
	± 0.5pF	D							
	EIA	C0G		25		± 5%	J		
	JIS	CH		-55 ~ + 125		20	0 ± 60ppm/°C	± 0.1pF	B
								± 0.25pF	C
EIA	C0H		25			± 0.5pF		D	
						± 5%		J	
CJ	JIS		CJ	-55 ~ + 125		20	0 ± 120ppm/°C	± 0.05pF	A
								± 0.1pF	B
	EIA	C0J			25			± 0.25pF	C
CK	JIS	CK		-55 ~ + 125	20		0 ± 250ppm/°C	± 0.05pF	A
								± 0.1pF	B
	EIA	C0K			25			± 0.25pF	C

⑥ Series code

• Low distortion design/Audible/Good bias Multilayer Ceramic Capacitor

Code	Series code
SD	Standard

• Medium-High Voltage Multilayer Ceramic Capacitor

Code	Series code
SD	Standard

⑦ Nominal capacitance

Code (example)	Nominal capacitance
0R5	0.5pF
010	1pF
100	10pF
101	100pF
102	1,000pF
103	0.01μF
104	0.1μF
105	1μF
106	10μF
107	100μF

Note : R=Decimal point

⑧ Capacitance tolerance

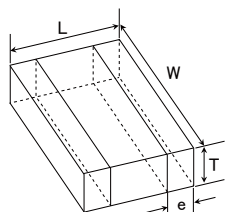
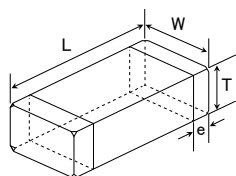
Code	Capacitance tolerance
A	± 0.05pF
B	± 0.1pF
C	± 0.25pF
D	± 0.5pF
G	± 2%
J	± 5%
K	± 10%
M	± 20%

⑨ Packaging

Code	Packaging
F	φ178mm Taping (2mm pitch)
T	φ178mm Taping (4mm pitch)
P	φ178mm Taping (4mm pitch, 1000 pcs/reel) 3225 type (Thickness code M)
R	φ178mm Embossed Taping 1005type (2mm pitch) 1608type (4mm pitch)
W	φ178mm Embossed Taping (1mm pitch) 0402type

⑩ Internal code

## STANDARD EXTERNAL DIMENSIONS



※LW reverse type

Type	JIS (mm)	EIA (inch)	Dimension [mm]				
			L	W	T	*1	e
MLAS□04	0402	01005	$0.4 \pm 0.02$	$0.2 \pm 0.02$	$0.2 \pm 0.02$	2	$0.1 \pm 0.03$
MLAS□06	0603	0201	$0.6 \pm 0.03$	$0.3 \pm 0.03$	$0.3 \pm 0.03$	3	$0.15 \pm 0.05$
MLAS□1L	1005	0402	$1.0 \pm 0.05$	$0.5 \pm 0.05$	$0.13 \pm 0.02$	H	$0.25 \pm 0.10$
					$0.18 \pm 0.02$	E	
					$0.2 \pm 0.02$	2	
					$0.3 \pm 0.03$	3	
MLAS□10	1005	0402	$1.0 \pm 0.05$	$0.5 \pm 0.05$	$0.5 \pm 0.05$	5	$0.25 \pm 0.10$
MLAY□1L	1005	0402	$1.0 \pm 0.05$	$0.5 \pm 0.05$	$0.3 \pm 0.03$	3	$0.25 \pm 0.10$
MLAY□10	1005	0402	$1.0 \pm 0.05$	$0.5 \pm 0.05$	$0.5 \pm 0.05$	5	$0.25 \pm 0.10$
MLRL□10 ※	0510	0204	$0.52 \pm 0.05$	$1.0 \pm 0.05$	$0.3 \pm 0.05$	3	$0.18 \pm 0.08$
MLAS□16	1608	0603	$1.6 \pm 0.10$	$0.8 \pm 0.10$	$0.45 \pm 0.05$	K	$0.35 \pm 0.25$
					$0.8 \pm 0.10$	8	
MLAY□16	1608	0603	$1.6 \pm 0.10$	$0.8 \pm 0.10$	$0.8 \pm 0.10$	8	$0.35 \pm 0.25$
MLRL□16 ※	0816	0306	$0.8 \pm 0.10$	$1.6 \pm 0.10$	$0.5 \pm 0.05$	5	$0.25 \pm 0.15$
MLAS□21	2012	0805	$2.0 \pm 0.10$	$1.25 \pm 0.10$	$0.85 \pm 0.10$	9	$0.5 \pm 0.25$
MLAY□21					$1.25 \pm 0.10$	G	
MLRL□21 ※	1220	0508	$1.25 \pm 0.15$	$2.0 \pm 0.15$	$0.85 \pm 0.10$	9	$0.3 \pm 0.2$
MLAS□31	3216	1206	$3.2 \pm 0.15$	$1.6 \pm 0.15$	$0.85 \pm 0.10$	9	$0.5 + 0.35 / - 0.25$
					$1.15 \pm 0.10$	Q	
					$1.6 \pm 0.20$	L	
MLAY□31	3216	1206	$3.2 \pm 0.15$	$1.6 \pm 0.15$	$1.15 \pm 0.10$	Q	$0.5 + 0.35 / - 0.25$
					$1.6 \pm 0.20$	L	
					$0.85 \pm 0.10$	9	
MLAS□32	3225	1210	$3.2 \pm 0.30$	$2.5 \pm 0.20$	$1.15 \pm 0.10$	Q	$0.6 \pm 0.3$
					$1.9 \pm 0.20$	N	
					$1.9 + 0.1 / - 0.20$	Y	
					$2.5 \pm 0.20$	M	
					$1.9 \pm 0.20$	N	
MLAY□32	3225	1210	$3.2 \pm 0.30$	$2.5 \pm 0.20$	$1.9 \pm 0.20$	N	$0.6 \pm 0.3$
					$2.5 \pm 0.20$	M	
					$2.0 + 0 / - 0.30$	Y	
MLAS□45	4532	1812	$4.5 \pm 0.40$	$3.2 \pm 0.30$	$2.0 + 0 / - 0.30$	Y	$0.6 \pm 0.4$
					$2.5 \pm 0.20$	M	

Note :※LW reverse type (MLRL), \*1.Thickness code

## ■ STANDARD QUANTITY

Type			Thickness		Standard quantity [pcs]	
Code	JIS(mm)	EIA(inch)	[mm]	Code	Paper tape	Embossed tape
04	0402	01005	0.2	2	—	40000
06	0603	0201	0.3	3	15000	—
1L	1005	0402	0.13	H	—	20000
			0.18	E	—	15000
			0.2	2	20000	—
			0.3	3	15000	—
10	1005	0402	0.5	5	10000	—
	0510 ※	0204 ※	0.3	3		
16	1608	0603	0.45	K	4000	—
			0.8	8		
	0816 ※	0306 ※	0.5	5	—	4000
21	2012	0805	0.85	9	4000	—
			1.25	G	—	3000
	1220 ※	0508 ※	0.85	9	4000	—
31	3216	1206	0.85	9	4000	—
			1.15	Q	—	3000
			1.6	L	—	2000
32	3225	1210	0.85	9	—	2000
			1.15	Q		
			1.9	N		
			2.0 max	Y		
			2.5	M		
45	4532	1812	2.0 max	Y	—	1000
			2.5	M	—	500

Note : ※.LW Reverse type (MLRL)



■ PARTS NUMBER

- All the Multilayer Ceramic Capacitors of the catalog lineup are RoHS Compliant.
- Capacitance tolerance code is applied to □ of part number.
- All the Multilayer Ceramic Capacitors in the catalog lineup are applicable for reflow-soldering. Please contact us for flow compatible products.

Note)  
 \*1 We may provide X7R/X7S for some items according to the individual specification.  
 \*2 The exchange of individual specification is necessary depending on the application and circuit condition. Please contact TAIYO YUDEN sales channels.  
 \*3 The size standard should look at Dimension, Thickness, Dimension tolerance, and STANDARD EXTERNAL DIMENSIONS.

**Multilayer Ceramic Capacitors (High dielectric type) for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)**

● 0402TYPE

【Temperature Characteristic B5(BJ): B (-25~+85°C)/X5R(-55~+85°C)】 0.2mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASE042SB5101□WNA01	EMK042 BJ101□C-W	16	X5R	100 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB5151□WNA01	EMK042 BJ151□C-W	16	X5R	150 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB5221□WNA01	EMK042 BJ221□C-W	16	X5R	220 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB5331□WNA01	EMK042 BJ331□C-W	16	X5R	330 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB5471□WNA01	EMK042 BJ471□C-W	16	X5R	470 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB5681□WNA01	EMK042 BJ681□C-W	16	X5R	680 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB5102□WNA01	EMK042 BJ102□C-W	16	B X5R	1000 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB5152□WNA01	EMK042 BJ152□C-W	16	X5R	1500 p	±10, ±20	10	150	0.2±0.02	
MLASE042SB5222□WNA01	EMK042 BJ222□C-W	16	X5R	2200 p	±10, ±20	10	150	0.2±0.02	
MLASE042SB5332□WNA01	EMK042 BJ332□C-W	16	X5R	3300 p	±10, ±20	10	150	0.2±0.02	
MLASE042SB5472□WNA01	EMK042 BJ472□C-W	16	X5R	4700 p	±10, ±20	10	150	0.2±0.02	
MLASE042SB5682□WNA01	EMK042 BJ682□C-W	16	X5R	6800 p	±10, ±20	10	150	0.2±0.02	
MLASE042SB5103□WNA01	EMK042 BJ103□C-W	16	X5R	0.01 μ	±10, ±20	10	150	0.2±0.02	
MLASL042SB5101□WNA01	LМК042 BJ101□C-W	10	X5R*1	100 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB5151□WNA01	LМК042 BJ151□C-W	10	X5R*1	150 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB5221□WNA01	LМК042 BJ221□C-W	10	X5R*1	220 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB5331□WNA01	LМК042 BJ331□C-W	10	X5R*1	330 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB5471□WNA01	LМК042 BJ471□C-W	10	X5R*1	470 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB5681□WNA01	LМК042 BJ681□C-W	10	X5R*1	680 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB5102□WNA01	LМК042 BJ102□C-W	10	B X5R*1	1000 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB5152□WNA01	LМК042 BJ152□C-W	10	X5R	1500 p	±10, ±20	10	150	0.2±0.02	
MLASL042SB5222□WNA01	LМК042 BJ222□C-W	10	X5R	2200 p	±10, ±20	10	150	0.2±0.02	
MLASL042SB5332□WNA01	LМК042 BJ332□C-W	10	X5R	3300 p	±10, ±20	10	150	0.2±0.02	
MLASL042SB5472□WNA01	LМК042 BJ472□C-W	10	X5R	4700 p	±10, ±20	10	150	0.2±0.02	
MLASL042SB5682□WNA01	LМК042 BJ682□C-W	10	X5R	6800 p	±10, ±20	10	150	0.2±0.02	
MLASL042SB5103□WNA01	LМК042 BJ103□C-W	10	X5R	0.01 μ	±10, ±20	10	150	0.2±0.02	
MLASJ042SB5152□WNA01	JMK042 BJ152□C-W	6.3	X5R*1	1500 p	±10, ±20	10	150	0.2±0.02	
MLASJ042SB5222□WNA01	JMK042 BJ222□C-W	6.3	X5R*1	2200 p	±10, ±20	10	150	0.2±0.02	
MLASJ042SB5332□WNA01	JMK042 BJ332□C-W	6.3	X5R*1	3300 p	±10, ±20	10	150	0.2±0.02	
MLASJ042SB5472□WNA01	JMK042 BJ472□C-W	6.3	X5R*1	4700 p	±10, ±20	10	150	0.2±0.02	
MLASJ042SB5682□WNA01	JMK042 BJ682□C-W	6.3	X5R*1	6800 p	±10, ±20	10	150	0.2±0.02	
MLASJ042SB5103□WNA01	JMK042 BJ103□C-W	6.3	X5R*1	0.01 μ	±10, ±20	10	150	0.2±0.02	
MLASJ042SB5223□WNA01	JMK042 BJ223□C-W	6.3	X5R	0.022 μ	±10, ±20	10	150	0.2±0.02	
MLASJ042SB5473□WNA01	JMK042 BJ473□C-W	6.3	X5R	0.047 μ	±10, ±20	10	150	0.2±0.02	
MLASJ042SB5104□WNA01	JMK042 BJ104□C-W	6.3	X5R	0.1 μ	±10, ±20	10	150	0.2±0.02	
MLASA042SB5473□WNA01	AMK042 BJ473□C-W	4	X5R	0.047 μ	±10, ±20	10	150	0.2±0.02	
MLASA042SB5104□WNA01	AMK042 BJ104□C-W	4	X5R	0.1 μ	±10, ±20	10	150	0.2±0.02	

【Temperature Characteristic B7 : X7R(-55~+125°C)】 0.2mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASE042SB7101□WNA01	EMK042 B7101□C-W	16	X7R	100 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB7151□WNA01	EMK042 B7151□C-W	16	X7R	150 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB7221□WNA01	EMK042 B7221□C-W	16	X7R	220 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB7331□WNA01	EMK042 B7331□C-W	16	X7R	330 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB7471□WNA01	EMK042 B7471□C-W	16	X7R	470 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB7681□WNA01	EMK042 B7681□C-W	16	X7R	680 p	±10, ±20	5	200	0.2±0.02	
MLASE042SB7102□WNA01	EMK042 B7102□C-W	16	X7R	1000 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB7101□WNA01	LМК042 B7101□C-W	10	X7R	100 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB7151□WNA01	LМК042 B7151□C-W	10	X7R	150 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB7221□WNA01	LМК042 B7221□C-W	10	X7R	220 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB7331□WNA01	LМК042 B7331□C-W	10	X7R	330 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB7471□WNA01	LМК042 B7471□C-W	10	X7R	470 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB7681□WNA01	LМК042 B7681□C-W	10	X7R	680 p	±10, ±20	5	200	0.2±0.02	
MLASL042SB7102□WNA01	LМК042 B7102□C-W	10	X7R	1000 p	±10, ±20	5	200	0.2±0.02	

▶ This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification.  
 For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (<http://www.ty-top.com/>).

## PARTS NUMBER

## 0603TYPE

【Temperature Characteristic B5(BJ): B(-25~+85°C)/X5R(-55~+85°C)】 0.3mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
								Rated voltage x %		
MLASU063SB5101[FNA01]	UMK063 BJ101[P-F]	50	B	X5R*1	100 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB5151[FNA01]	UMK063 BJ151[P-F]	50	B	X5R*1	150 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB5221[FNA01]	UMK063 BJ221[P-F]	50	B	X5R*1	220 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB5331[FNA01]	UMK063 BJ331[P-F]	50	B	X5R*1	330 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB5471[FNA01]	UMK063 BJ471[P-F]	50	B	X5R*1	470 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB5681[FNA01]	UMK063 BJ681[P-F]	50	B	X5R*1	680 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB5102[FNA01]	UMK063 BJ102[P-F]	50	B	X5R*1	1000 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB5152[FNA01]	UMK063 BJ152[P-F]	50	B	X5R	1500 p	±10, ±20	5	200	0.3±0.03	
MLASU063SB5222[FNA01]	UMK063 BJ222[P-F]	50	B	X5R	2200 p	±10, ±20	5	200	0.3±0.03	
MLASU063SB5332[FNA01]	UMK063 BJ332[P-F]	50	B	X5R	3300 p	±10, ±20	5	200	0.3±0.03	
MLASU063SB5472[FNA01]	UMK063 BJ472[P-F]	50	B	X5R	4700 p	±10, ±20	5	200	0.3±0.03	
MLASU063SB5682[FNA01]	UMK063 BJ682[P-F]	50	B	X5R	6800 p	±10, ±20	5	200	0.3±0.03	
MLASU063SB5103[FNA01]	UMK063 BJ103[P-F]	50	B	X5R	0.01 μ	±10, ±20	5	200	0.3±0.03	
MLASG063SB5104[FNA01]	GMK063 BJ104[P-F]	35		X5R	0.1 μ	±10, ±20	10	150	0.3±0.03	
MLAST063SB5152[FNA01]	TMK063 BJ152[P-F]	25	B	X5R	1500 p	±10, ±20	5	200	0.3±0.03	
MLAST063SB5222[FNA01]	TMK063 BJ222[P-F]	25	B	X5R	2200 p	±10, ±20	5	200	0.3±0.03	
MLAST063SB5332[FNA01]	TMK063 BJ332[P-F]	25	B	X5R	3300 p	±10, ±20	5	200	0.3±0.03	
MLAST063SB5472[FNA01]	TMK063 BJ472[P-F]	25	B	X5R	4700 p	±10, ±20	5	200	0.3±0.03	
MLAST063SB5682[FNA01]	TMK063 BJ682[P-F]	25	B	X5R	6800 p	±10, ±20	5	200	0.3±0.03	
MLAST063SB5103[FNA01]	TMK063 BJ103[P-F]	25	B	X5R	0.01 μ	±10, ±20	5	200	0.3±0.03	
MLAST063SB5223[FNA01]	TMK063 BJ223[P-F]	25	B	X5R	0.022 μ	±10, ±20	7.5	200	0.3±0.03	
MLAST063AB5104[FNA01]	TMK063ABJ104[P-F]	25		X5R	0.1 μ	±10, ±20	10	150	0.3±0.05	
MLASE063SB5152[FNA01]	EMK063 BJ152[P-F]	16	B	X5R*1	1500 p	±10, ±20	5	200	0.3±0.03	
MLASE063SB5222[FNA01]	EMK063 BJ222[P-F]	16	B	X5R*1	2200 p	±10, ±20	5	200	0.3±0.03	
MLASE063SB5332[FNA01]	EMK063 BJ332[P-F]	16	B	X5R*1	3300 p	±10, ±20	5	200	0.3±0.03	
MLASE063SB5472[FNA01]	EMK063 BJ472[P-F]	16	B	X5R*1	4700 p	±10, ±20	5	200	0.3±0.03	
MLASE063SB5682[FNA01]	EMK063 BJ682[P-F]	16	B	X5R*1	6800 p	±10, ±20	5	200	0.3±0.03	
MLASE063SB5103[FNA01]	EMK063 BJ103[P-F]	16	B	X5R*1	0.01 μ	±10, ±20	5	200	0.3±0.03	
MLASE063SB5153[FNA01]	EMK063 BJ153[P-F]	16		X5R	0.015 μ	±10, ±20	7.5	200	0.3±0.03	
MLASE063SB5223[FNA01]	EMK063 BJ223[P-F]	16	B	X5R	0.022 μ	±10, ±20	7.5	200	0.3±0.03	
MLASE063SB5333[FNA01]	EMK063 BJ333[P-F]	16		X5R	0.033 μ	±10, ±20	7.5	150	0.3±0.03	
MLASE063SB5473[FNA01]	EMK063 BJ473[P-F]	16		X5R	0.047 μ	±10, ±20	7.5	150	0.3±0.03	
MLASE063SB5683[FNA01]	EMK063 BJ683[P-F]	16		X5R	0.068 μ	±10, ±20	10	150	0.3±0.03	
MLASE063SB5104[FNA01]	EMK063 BJ104[P-F]	16		X5R	0.1 μ	±10, ±20	10	150	0.3±0.03	
MLASE063SB5224[FNA01]	EMK063 BJ224[P-F]	16		X5R	0.22 μ	±10, ±20	10	150	0.3±0.03	
MLASE063BB5474[FNB33]	EMK063BBJ474[PLF]	16		X5R	0.47 μ	±10, ±20	10	150	0.3±0.09	
MLASL063SB5223[FNA01]	LМК063 BJ223[P-F]	10	B	X5R	0.022 μ	±10, ±20	7.5	150	0.3±0.03	
MLASL063SB5333[FNA01]	LМК063 BJ333[P-F]	10		X5R	0.033 μ	±10, ±20	7.5	150	0.3±0.03	
MLASL063SB5473[FNA01]	LМК063 BJ473[P-F]	10		X5R	0.047 μ	±10, ±20	7.5	150	0.3±0.03	
MLASL063SB5683[FNA01]	LМК063 BJ683[P-F]	10		X5R	0.068 μ	±10, ±20	10	150	0.3±0.03	
MLASL063SB5104[FNA01]	LМК063 BJ104[P-F]	10		X5R	0.1 μ	±10, ±20	10	150	0.3±0.03	
MLASL063SB5224[FNA01]	LМК063 BJ224[P-F]	10		X5R	0.22 μ	±10, ±20	10	150	0.3±0.03	
MLASL063BB5474[FNB33]	LМК063BBJ474[PLF]	10		X5R	0.47 μ	±10, ±20	10	150	0.3±0.09	
MLASL063BB5105MFNB33	LМК063BBJ105MPLF	10		X5R	1 μ	±20	10	150	0.3±0.09	
MLASJ063SB5104[FNA01]	JMK063 BJ104[P-F]	6.3		X5R	0.1 μ	±10, ±20	10	150	0.3±0.03	
MLASJ063SB5224[FNA01]	JMK063 BJ224[P-F]	6.3		X5R	0.22 μ	±10, ±20	10	150	0.3±0.03	
MLASJ063SB5334MFNA01	JMK063 BJ334MP-F	6.3		X5R	0.33 μ	±20	10	150	0.3±0.03	
MLASJ063SB5474[FNA01]	JMK063 BJ474[P-F]	6.3		X5R	0.47 μ	±10, ±20	10	150	0.3±0.03	
MLASJ063AB5105[FNA01]	JMK063ABJ105[P-F]	6.3		X5R	1 μ	±10, ±20	10	150	0.3±0.05	
MLASP063EB5475MFNA01	PMK063EBJ475MP-F	2.5		X5R	4.7 μ	±20	10	150	0.3+0.25/-0	

【Temperature Characteristic C6 : X6S(-55~+105°C)】 0.3mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
								Rated voltage x %		
MLAST063SC6104[FNA01]	TMK063 C6104[P-F]	25		X6S	0.1 μ	±10, ±20	10	150	0.3±0.03	
MLASE063AC6104[FNA01]	EMK063AC6104[P-F]	16		X6S	0.1 μ	±10, ±20	10	150	0.3±0.05	
MLASL063SC6104[FNA01]	LМК063 C6104[P-F]	10		X6S	0.1 μ	±10, ±20	10	150	0.3±0.03	
MLASL063SC6224[FNA01]	LМК063 C6224[P-F]	10		X6S	0.22 μ	±10, ±20	10	150	0.3±0.03	
MLASL063BC6474[FNB33]	LМК063BC6474[PLF]	10		X6S	0.47 μ	±10, ±20	10	150	0.3±0.09	
MLASJ063SC6104[FNA01]	JMK063 C6104[P-F]	6.3		X6S	0.1 μ	±10, ±20	10	150	0.3±0.03	
MLASJ063SC6224[FNA01]	JMK063 C6224[P-F]	6.3		X6S	0.22 μ	±10, ±20	10	150	0.3±0.03	
MLASJ063BC6474[FNA01]	JMK063BC6474[P-F]	6.3		X6S	0.47 μ	±10, ±20	10	150	0.3±0.09	
MLASJ063BC6105MFNA01	JMK063BC6105MP-F	6.3		X6S	1 μ	±20	10	150	0.3±0.09	
MLASA063SC6474[FNA01]	AMK063 C6474[P-F]	4		X6S	0.47 μ	±10, ±20	10	150	0.3±0.03	
MLASA063AC6105[FNA01]	AMK063AC6105[P-F]	4		X6S	1 μ	±10, ±20	10	150	0.3±0.05	

## PARTS NUMBER

## 【Temperature Characteristic B7 : X7R (−55~+125°C)】 0.3mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU063SB7101□FNA01	UMK063 B7101□P-F	50	X7R	100 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB7151□FNA01	UMK063 B7151□P-F	50	X7R	150 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB7221□FNA01	UMK063 B7221□P-F	50	X7R	220 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB7331□FNA01	UMK063 B7331□P-F	50	X7R	330 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB7471□FNA01	UMK063 B7471□P-F	50	X7R	470 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB7681□FNA01	UMK063 B7681□P-F	50	X7R	680 p	±10, ±20	3.5	200	0.3±0.03	
MLASU063SB7102□FNA01	UMK063 B7102□P-F	50	X7R	1000 p	±10, ±20	3.5	200	0.3±0.03	
MLAST063SB7152□FNA01	TMK063 B7152□P-F	25	X7R	1500 p	±10, ±20	5	200	0.3±0.03	
MLAST063SB7222□FNA01	TMK063 B7222□P-F	25	X7R	2200 p	±10, ±20	5	200	0.3±0.03	
MLAST063SB7332□FNA01	TMK063 B7332□P-F	25	X7R	3300 p	±10, ±20	5	200	0.3±0.03	
MLAST063SB7472□FNA01	TMK063 B7472□P-F	25	X7R	4700 p	±10, ±20	5	200	0.3±0.03	
MLAST063SB7682□FNA01	TMK063 B7682□P-F	25	X7R	6800 p	±10, ±20	5	200	0.3±0.03	
MLAST063SB7103□FNA01	TMK063 B7103□P-F	25	X7R	0.01 μ	±10, ±20	5	200	0.3±0.03	
MLASE063SB7152□FNA01	EMK063 B7152□P-F	16	X7R	1500 p	±10, ±20	5	200	0.3±0.03	
MLASE063SB7222□FNA01	EMK063 B7222□P-F	16	X7R	2200 p	±10, ±20	5	200	0.3±0.03	
MLASE063SB7332□FNA01	EMK063 B7332□P-F	16	X7R	3300 p	±10, ±20	5	200	0.3±0.03	
MLASE063SB7472□FNA01	EMK063 B7472□P-F	16	X7R	4700 p	±10, ±20	5	200	0.3±0.03	
MLASE063SB7682□FNA01	EMK063 B7682□P-F	16	X7R	6800 p	±10, ±20	5	200	0.3±0.03	
MLASE063SB7103□FNA01	EMK063 B7103□P-F	16	X7R	0.01 μ	±10, ±20	5	200	0.3±0.03	
MLASE063SB7223□FNA01	EMK063 B7223□P-F	16	X7R	0.022 μ	±10, ±20	7.5	150	0.3±0.03	

## ● 1005TYPE

## 【Temperature Characteristic B5(BJ): B (−25~+85°C)/X5R (−55~+85°C)】 0.5mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note	
							Rated voltage x %			
MLASU105SB5223□FNA01	UMK105 BJ223□V-F	50	X5R	0.022 μ	±10, ±20	5	200	0.5±0.05		
MLASU105SB5473□FNA01	UMK105 BJ473□V-F	50	X5R	0.047 μ	±10, ±20	5	200	0.5±0.05		
MLASU105SB5104□FNA01	UMK105 BJ104□V-F	50	X5R	0.1 μ	±10, ±20	10	150	0.5±0.05		
MLASU105SB5224□FNA01	UMK105 BJ224□V-F	50	X5R	0.22 μ	±10, ±20	10	150	0.5±0.05		
MLASU105AB5474□FNA01	UMK105ABJ474□V-F	50	X5R	0.47 μ	±10, ±20	10	150	0.5±0.10		
MLASU105CB5105□FNA01	UMK105CBJ105□V-F	50	X5R	1 μ	±10, ±20	10	150	0.5+0.20/-0		
MLASG105SB5104□FNA01	GMK105 BJ104□V-F	35	B	0.1 μ	±10, ±20	5	150	0.5±0.05		
MLASG105AB5105□FNA01	GMK105ABJ105□V-F	35	X5R	1 μ	±10, ±20	10	150	0.5±0.10		
MLAST105SB5153□FNA01	TMK105 BJ153□V-F	25	B	X5R*1	0.015 μ	±10, ±20	3.5	200	0.5±0.05	
MLAST105SB5223□FNA01	TMK105 BJ223□V-F	25	B	X5R*1	0.022 μ	±10, ±20	3.5	200	0.5±0.05	
MLAST105SB5333□FNA01	TMK105 BJ333□V-F	25	B	X5R*1	0.033 μ	±10, ±20	3.5	150	0.5±0.05	
MLAST105SB5473□FNA01	TMK105 BJ473□V-F	25	B	X5R*1	0.047 μ	±10, ±20	3.5	150	0.5±0.05	
MLAST105SB5104□FNA01	TMK105 BJ104□V-F	25	B	X5R	0.1 μ	±10, ±20	5	150	0.5±0.05	
MLAST105SB5224□FNA01	TMK105 BJ224□V-F	25	X5R	0.22 μ	±10, ±20	10	200	0.5±0.05		
MLAST105AB5474□FNA01	TMK105ABJ474□V-F	25	X5R	0.47 μ	±10, ±20	10	200	0.5±0.10		
MLAST105SB5105□FNA01	TMK105 BJ105□V-F	25	X5R	1 μ	±10, ±20	10	150	0.5±0.05		
MLAST105CB5225□FNA01	TMK105CBJ225□V-F	25	X5R	2.2 μ	±10, ±20	10	150	0.5+0.20/-0		
MLASE105SB5224□FNA01	EMK105 BJ224□V-F	16	B	X5R	0.22 μ	±10, ±20	5	150	0.5±0.05	
MLASE105AB5474□FNA01	EMK105ABJ474□V-F	16	X5R	0.47 μ	±10, ±20	10	200	0.5±0.10		
MLASE105SB5105□FNA01	EMK105 BJ105□V-F	16	X5R	1 μ	±10, ±20	10	150	0.5±0.05		
MLASE105AB5225□FNA01	EMK105ABJ225□V-F	16	X5R	2.2 μ	±10, ±20	10	150	0.5±0.10		
MLASL105SB5225□FNA01	LKM105 BJ225□V-F	10	X5R	2.2 μ	±10, ±20	10	150	0.5±0.05		
MLASL105BB5475MFB33	LKM105BBJ475MFLF	10	X5R	4.7 μ	±20	10	150	0.5+0.15/-0.05		
MLASJ105SB5225□FNA01	JMK105 BJ225□V-F	6.3	X5R	2.2 μ	±10, ±20	10	150	0.5±0.05		
MLASJ105BB5475MFA01	JMK105BBJ475MV-F	6.3	X5R	4.7 μ	±20	10	150	0.5+0.15/-0.05		

## 【Temperature Characteristic B5(BJ): B (−25~+85°C)/X5R (−55~+85°C)】 0.3mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note	
							Rated voltage x %			
MLASU1L3YB5104□FNA01	UMK105 BJ104□P-F	50	X5R	0.1 μ	±10, ±20	10	150	0.3±0.03		
MLAST1L3YB5103□FNA01	TMK105 BJ103□P-F	25	B	X5R	0.01 μ	±10, ±20	5	150	0.3±0.03	
MLAST1L3YB5104□FNA01	TMK105 BJ104□P-F	25	X5R	0.1 μ	±10, ±20	10	150	0.3±0.03		
MLAST1L3YB5224□FNA01	TMK105 BJ224□P-F	25	X5R	0.22 μ	±10, ±20	10	150	0.3±0.03		
MLAST1L3YB5474□FNA01	TMK105 BJ474□P-F	25	X5R	0.47 μ	±10, ±20	10	150	0.3±0.03		
MLASE1L3YB5474□FNA01	EMK105 BJ474□P-F	16	X5R	0.47 μ	±10, ±20	10	150	0.3±0.03		
MLASL1L3YB5105□FNB33	LKM105 BJ105□PLF	10	X5R	1 μ	±10, ±20	10	150	0.3±0.03		
MLASJ1L3YB5105□FNA01	JMK105 BJ105□P-F	6.3	X5R	1 μ	±10, ±20	10	150	0.3±0.03		
MLASA1L3YB5225MFA01	AMK105 BJ225MP-F	4	X5R	2.2 μ	±20	10	150	0.3±0.03		

## 【Temperature Characteristic B5(BJ): X5R (−55~+85°C)】 0.2mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASL1L2XB5104□FNA01	LKM105 BJ104□C-F	10	X5R	0.1 μ	±10, ±20	10	150	0.2±0.02	
MLASJ1L2XB5224□FNA01	JMK105 BJ224□C-F	6.3	X5R	0.22 μ	±10, ±20	10	150	0.2±0.02	
MLASJ1L2XB5474□FNA01	JMK105 BJ474□C-F	6.3	X5R	0.47 μ	±10, ±20	10	150	0.2±0.02	
MLASJ1L2XB5105MFA01	JMK105 BJ105MC-F	6.3	X5R	1 μ	±20	10	150	0.2±0.02	

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## 【Temperature Characteristic B5(BJ): X5R(-55~+85°C)】 0.1mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASL1LEXB5104[RNA01	LMK105 BJ104[E-R	10	X5R	0.1 μ	±10, ±20	10	150	0.18±0.02	
MLASJ1LEXB5224[RNA01	JMK105 BJ224[E-R	6.3	X5R	0.22 μ	±10, ±20	10	150	0.18±0.02	
MLASJ1LEXB5474[RNA01	JMK105 BJ474[E-R	6.3	X5R	0.47 μ	±10, ±20	10	150	0.18±0.02	
MLASA1LEXB5105MRNA01	AMK105 BJ105ME-R	4	X5R	1 μ	±20	10	150	0.18±0.02	

## 【Temperature Characteristic B5(BJ): X5R(-55~+85°C)】 0.13mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASL1LHXB5104MRNA01	LMK105 BJ104MH-R	10	X5R	0.1 μ	±20	10	150	0.13±0.02	
MLASJ1LHXB5224MRNA01	JMK105 BJ224MH-R	6.3	X5R	0.22 μ	±20	10	150	0.13±0.02	
MLASA1LHXB5474MRNA01	AMK105 BJ474MH-R	4	X5R	0.47 μ	±20	10	150	0.13±0.02	

## 【Temperature Characteristic C6 : X6S(-55~+105°C)】 0.5mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASG105CC6105[FNA01	GMK105CC6105[V-F	35	X6S	1 μ	±10, ±20	10	150	0.5+0.20/-0	
MLAST105AC6105[FNA01	TMK105AC6105[V-F	25	X6S	1 μ	±10, ±20	10	150	0.5±0.10	
MLAST105CC6105MFNA01	TMK105CC6105MV-F	25	X6S	1 μ	±20	10	150	0.5+0.20/-0	
MLASE105SC6105[FNA01	EMK105 C6105[V-F	16	X6S	1 μ	±10, ±20	10	150	0.5±0.05	
MLASE105CC6225[FNA01	EMK105CC6225[V-F	16	X6S	2.2 μ	±10, ±20	10	150	0.5+0.20/-0	
MLASL105SC6105[FNA01	LMK105 C6105[V-F	10	X6S	1 μ	±10, ±20	10	200	0.5±0.05	
MLASL105AC6225[FNA01	LMK105AC6225[V-F	10	X6S	2.2 μ	±10, ±20	10	150	0.5±0.10	
MLASJ105SC6225[FNA01	JMK105 C6225[V-F	6.3	X6S	2.2 μ	±10, ±20	10	150	0.5±0.05	
MLASJ105BC6475MFNA01	JMK105BC6475MV-F	6.3	X6S	4.7 μ	±20	10	150	0.5+0.15/-0.05	
MLASA105BC6475MFNA01	AMK105BC6475MV-F	4	X6S	4.7 μ	±20	10	200	0.5+0.15/-0.05	

## 【Temperature Characteristic B7 : X7R(-55~+125°C)】 0.5mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU105SB7152[FNA01	UMK105 B7152[V-F	50	X7R	1500 p	±10, ±20	2.5	200	0.5±0.05	
MLASU105SB7222[FNA01	UMK105 B7222[V-F	50	X7R	2200 p	±10, ±20	2.5	200	0.5±0.05	
MLASU105SB7332[FNA01	UMK105 B7332[V-F	50	X7R	3300 p	±10, ±20	2.5	200	0.5±0.05	
MLASU105SB7472[FNA01	UMK105 B7472[V-F	50	X7R	4700 p	±10, ±20	2.5	150	0.5±0.05	
MLASU105SB7682[FNA01	UMK105 B7682[V-F	50	X7R	6800 p	±10, ±20	2.5	150	0.5±0.05	
MLASU105SB7103[FNA01	UMK105 B7103[V-F	50	X7R	0.01 μ	±10, ±20	3.5	150	0.5±0.05	
MLASU105SB7223[FNB25	UMK105 B7223[V-FR	50	X7R	0.022 μ	±10, ±20	10	200	0.5±0.05	
MLASU105SB7473[FNB25	UMK105 B7473[V-FR	50	X7R	0.047 μ	±10, ±20	10	200	0.5±0.05	
MLASU105SB7104[FNB25	UMK105 B7104[V-FR	50	X7R	0.1 μ	±10, ±20	10	150	0.5±0.05	
MLAST105SB7223[FNA01	TMK105 B7223[V-F	25	X7R	0.022 μ	±10, ±20	3.5	150	0.5±0.05	
MLAST105SB7473[FNA01	TMK105 B7473[V-F	25	X7R	0.047 μ	±10, ±20	3.5	150	0.5±0.05	
MLAST105SB7104[FNB25	TMK105 B7104[V-FR	25	X7R	0.1 μ	±10, ±20	10	200	0.5±0.05	
MLAST105SB7224[FNB25	TMK105 B7224[V-FR	25	X7R	0.22 μ	±10, ±20	10	150	0.5±0.05	
MLASE105SB7223[FNA01	EMK105 B7223[V-F	16	X7R	0.022 μ	±10, ±20	3.5	200	0.5±0.05	
MLASE105SB7473[FNA01	EMK105 B7473[V-F	16	X7R	0.047 μ	±10, ±20	3.5	200	0.5±0.05	
MLASE105SB7104[FNA01	EMK105 B7104[V-F	16	X7R	0.1 μ	±10, ±20	5	150	0.5±0.05	
MLASE105SB7224[FNB25	EMK105 B7224[V-FR	16	X7R	0.22 μ	±10, ±20	10	150	0.5±0.05	
MLASL105SB7224[FNB25	LMK105 B7224[V-FR	10	X7R	0.22 μ	±10, ±20	10	150	0.5±0.05	
MLASL105SB7474[FNA01	LMK105 B7474[V-F	10	X7R	0.47 μ	±10, ±20	10	150	0.5±0.05	
MLASJ105SB7224[FNA01	JMK105 B7224[V-F	6.3	X7R	0.22 μ	±10, ±20	5	150	0.5±0.05	
MLASJ105SB7474[FNA01	JMK105 B7474[V-F	6.3	X7R	0.47 μ	±10, ±20	10	150	0.5±0.05	

## ● 1608TYPE

## 【Temperature Characteristic B5(BJ): X5R(-55~+85°C)】 0.8mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU168AB5474[TNA01	UMK107ABJ474[A-T	50	X5R	0.47 μ	±10, ±20	10	150	0.8+0.15/-0.05	
MLASU168BB5105[TNA01	UMK107 BJ105[A-T	50	X5R	1 μ	±10, ±20	10	150	0.8±0.10	
MLASU168BB5225[TNA01	UMK107BBJ225[A-T	50	X5R	2.2 μ	±10, ±20	10	150	0.8+0.20/-0	
MLASG168BB5475[TNA01	GMK107BBJ475[A-T	35	X5R	4.7 μ	±10, ±20	10	150	0.8+0.20/-0	
MLAST168AB5225[TNA01	TMK107ABJ225[A-T	25	X5R	2.2 μ	±10, ±20	10	150	0.8+0.15/-0.05	
MLAST168BB5475[TNA01	TMK107BBJ475[A-T	25	X5R	4.7 μ	±10, ±20	10	150	0.8+0.20/-0	
MLAST168BB5106MTNA01	TMK107BBJ106MA-T	25	X5R	10 μ	±20	10	150	0.8+0.20/-0	
MLASE168AB5475[TNA01	EMK107ABJ475[A-T	16	X5R	4.7 μ	±10, ±20	10	150	0.8+0.15/-0.05	
MLASE168BB5106MTNA01	EMK107BBJ106MA-T	16	X5R	10 μ	±20	10	150	0.8+0.20/-0	
MLASL168BB5106[TNB33	LMK107BBJ106[ALT	10	X5R	10 μ	±10, ±20	10	150	0.8+0.20/-0	
MLASL168BB5226MTNA01	LMK107BBJ226MA-T	10	X5R	22 μ	±20	10	150	0.8+0.20/-0	
MLASJ168AB5106[TNA01	JMK107ABJ106[A-T	6.3	X5R	10 μ	±10, ±20	10	150	0.8+0.15/-0.05	
MLASJ168BB5226MTNA01	JMK107BBJ226MA-T	6.3	X5R	22 μ	±20	10	150	0.8+0.20/-0	
MLASA168BB5476MRCA01	AMK107BBJ476MA-RE	4	X5R	47 μ	±20	20	150	0.8+0.20/-0	

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## 【Temperature Characteristic B5(BJ): X5R(-55~+85°C)】 0.45mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLAST16KTB5105□TNA01	TMK107 BJ105□K-T	25	X5R	1 μ	±10, ±20	10	150	0.45±0.05	
MLASE16KTB5105□TNA01	EMK107 BJ105□K-T	16	X5R	1 μ	±10, ±20	10	150	0.45±0.05	
MLASE16KJB5225□TNA01	EMK107BJ225□K-T	16	X5R	2.2 μ	±10, ±20	10	150	0.45±0.05	
MLASL16KTB5105□TNA01	LMK107 BJ105□K-T	10	X5R	1 μ	±10, ±20	10	150	0.45±0.05	
MLASL16KTB5225□TNA01	LMK107 BJ225□K-T	10	X5R	2.2 μ	±10, ±20	10	150	0.45±0.05	
MLASL16KJB5475MTNB33	LMK107BJ475MKLT	10	X5R	4.7 μ	±20	10	150	0.45±0.05	
MLASJ16KTB5105□TNA01	JMK107 BJ105□K-T	6.3	X5R	1 μ	±10, ±20	10	150	0.45±0.05	
MLASJ16KTB5225□TNA01	JMK107 BJ225□K-T	6.3	X5R	2.2 μ	±10, ±20	10	150	0.45±0.05	
MLASJ16KTB5475MTNA01	JMK107 BJ475MK-T	6.3	X5R	4.7 μ	±20	10	150	0.45±0.05	

## 【Temperature Characteristic C6 : X6S(-55~+105°C)】 0.8mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLAST168BC6225□TNA01	TMK107BC6225□A-T	25	X6S	2.2 μ	±10, ±20	10	150	0.8+0.20/-0	
MLASE168SC6105□TNA01	EMK107 C6105□A-T	16	X6S	1 μ	±10, ±20	5	150	0.8±0.10	
MLASE168BC6225□TNA01	EMK107BC6225□A-T	16	X6S	2.2 μ	±10, ±20	10	150	0.8+0.20/-0	
MLASE168BC6475□TNA01	EMK107BC6475□A-T	16	X6S	4.7 μ	±10, ±20	10	150	0.8+0.20/-0	
MLASE168BC6106MTNA01	EMK107BC6106MA-T	16	X6S	10 μ	±20	10	150	0.8+0.20/-0	
MLASL168SC6105□TNA01	LMK107 C6105□A-T	10	X6S	1 μ	±10, ±20	5	150	0.8±0.10	
MLASL168AC6475□TNA01	LMK107AC6475□A-T	10	X6S	4.7 μ	±10, ±20	10	150	0.8+0.15/-0.05	
MLASL168BC6106MTNA01	LMK107BC6106MA-T	10	X6S	10 μ	±20	10	150	0.8+0.20/-0	
MLASJ168SC6475□TNA01	JMK107 C6475□A-T	6.3	X6S	4.7 μ	±10, ±20	10	150	0.8±0.10	
MLASJ168BC6106MTNA01	JMK107BC6106MA-T	6.3	X6S	10 μ	±20	10	150	0.8+0.20/-0	
MLASA168BC6226MTNA01	AMK107BC6226MA-T	4	X6S	22 μ	±20	10	150	0.8+0.20/-0	
MLASA168BC6476MRCA01	AMK107BC6476MA-RE	4	X6S	47 μ	±20	20	150	0.8+0.20/-0	

## 【Temperature Characteristic B7 : X7R(-55~+125°C)】 0.8mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU168SB7224□TNB25	UMK107 B7224□A-TR	50	X7R	0.22 μ	±10, ±20	10	150	0.8±0.10	
MLASU168SB7474□TNB25	UMK107 B7474□A-TR	50	X7R	0.47 μ	±10, ±20	10	150	0.8±0.10	
MLASU168AB7105□TNA01	UMK107AB7105□A-T	50	X7R	1 μ	±10, ±20	10	150	0.8+0.15/-0.05	
MLAST168SB7474□TNB25	TMK107 B7474□A-TR	25	X7R	0.47 μ	±10, ±20	10	150	0.8±0.10	
MLAST168SB7105□TNA01	TMK107 B7105□A-T	25	X7R	1 μ	±10, ±20	10	150	0.8±0.10	
MLASE168SB7474□TNA01	EMK107 B7474□A-T	16	X7R	0.47 μ	±10, ±20	3.5	150	0.8±0.10	
MLASE168SB7105□TNA01	EMK107 B7105□A-T	16	X7R	1 μ	±10, ±20	5	150	0.8±0.10	
MLASE168BB7225□TNA01	EMK107BB7225□A-T	16	X7R	2.2 μ	±10, ±20	10	150	0.8+0.20/-0	
MLASL168SB7225□TNB25	LMK107 B7225□A-TR	10	X7R	2.2 μ	±10, ±20	10	150	0.8±0.10	
MLASJ168SB7225□TNB25	JMK107 B7225□A-TR	6.3	X7R	2.2 μ	±10, ±20	10	200	0.8±0.10	
MLASJ168BB7475□TNA01	JMK107BB7475□A-T	6.3	X7R	4.7 μ	±10, ±20	10	150	0.8+0.20/-0	

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## 【Temperature Characteristic B5(BJ): X5R(-55~+85°C)】 1.25mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU21GBB5475□TNA01	UMK212BBJ475□G-T	50	X5R	4.7 μ	±10, ±20	10	150	1.25+0.20/-0	
MLASG21GBB5106□TNA01	GMK212BBJ106□G-T	35	X5R	10 μ	±10, ±20	10	150	1.25+0.20/-0	
MLAST21GAB5475□TNA01	TMK212ABJ475□G-T	25	X5R	4.7 μ	±10, ±20	10	150	1.25+0.15/-0.05	
MLAST21GBB5106□TNA01	TMK212BBJ106□G-T	25	X5R	10 μ	±10, ±20	10	150	1.25+0.20/-0	
MLAST21GBB5226MTNC12	TMK212BBJ226MG-TT	25	X5R	22 μ	±20	10	150	1.25+0.20/-0	
MLASE21GAB5106□TNA01	EMK212ABJ106□G-T	16	X5R	10 μ	±10, ±20	10	150	1.25+0.15/-0.05	
MLASE21GBB5226MTNA01	EMK212BBJ226MG-T	16	X5R	22 μ	±20	10	150	1.25+0.20/-0	
MLASL21GBB5226MTNA01	LMK212BBJ226MG-T	10	X5R	22 μ	±20	10	150	1.25+0.20/-0	
MLASL21GAB5476MTNA01	LMK212BBJ476MG-T	10	X5R	47 μ	±20	10	150	1.25+0.20/-0	
MLASJ21GAB5226□TNA01	JMK212ABJ226□G-T	6.3	X5R	22 μ	±10, ±20	10	150	1.25+0.15/-0.05	
MLASJ21GBB5476MTNA01	JMK212BBJ476MG-T	6.3	X5R	47 μ	±20	10	150	1.25+0.20/-0	
MLASA21GBB5107MTCA01	AMK212BBJ107MG-TE	4	X5R	100 μ	±20	20	150	1.25+0.20/-0	

## PARTS NUMBER

## 【Temperature Characteristic B5(BJ): B(-25~+85°C)/X5R(-55~+85°C)】0.85mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU219JB5105□TNA01	UMK212ABJ105□D-T	50	X5R	1 μ	±10, ±20	10	150	0.85±0.10	
MLASU219LB5225□TNA01	UMK212BBJ225□D-T	50	X5R	2.2 μ	±10, ±20	10	150	0.85±0.10	
MLASG219LB5475□TNA01	GMK212BBJ475□D-T	35	X5R	4.7 μ	±10, ±20	10	150	0.85±0.10	
MLAST219SB5474□TNA01	TMK212 BJ474□D-T	25	B X5R	0.47 μ	±10, ±20	3.5	200	0.85±0.10	
MLAST219SB5105□TNA01	TMK212 BJ105□D-T	25	B X5R	1 μ	±10, ±20	5	200	0.85±0.10	
MLAST219JB5225□TNA01	TMK212ABJ225□D-T	25	X5R	2.2 μ	±10, ±20	5	150	0.85±0.10	
MLAST219LB5475□TNA01	TMK212BBJ475□D-T	25	X5R	4.7 μ	±10, ±20	10	150	0.85±0.10	
MLAST219LB5106□TNA01	TMK212BBJ106□D-T	25	X5R	10 μ	±10, ±20	10	150	0.85±0.10	
MLASE219SB5105□TNA01	EMK212 BJ105□D-T	16	X5R*1	1 μ	±10, ±20	5	200	0.85±0.10	
MLASE219JB5225□TNA01	EMK212ABJ225□D-T	16	X5R*1	2.2 μ	±10, ±20	5	200	0.85±0.10	
MLASE219SB5475□TNA01	EMK212 BJ475□D-T	16	X5R	4.7 μ	±10, ±20	10	150	0.85±0.10	
MLASE219JB5106□TNA01	EMK212ABJ106□D-T	16	X5R	10 μ	±10, ±20	10	150	0.85±0.10	
MLASL219SB5105□TNA01	LМК212 BJ105□D-T	10	B X5R*1	1 μ	±10, ±20	3.5	200	0.85±0.10	
MLASL219SB5225□TNA01	LМК212 BJ225□D-T	10	X5R*1	2.2 μ	±10, ±20	5	200	0.85±0.10	
MLASL219JB5106□TNA01	LМК212ABJ106□D-T	10	X5R	10 μ	±10, ±20	10	150	0.85±0.10	
MLASL219LB5226MTNA01	LМК212BBJ226MD-T	10	X5R	22 μ	±20	10	150	0.85±0.10	
MLASJ219JB5106□TNA01	JMK212ABJ106□D-T	6.3	X5R	10 μ	±10, ±20	10	200	0.85±0.10	
MLASJ219JB5226MTNA01	JMK212ABJ226MD-T	6.3	X5R	22 μ	±20	10	150	0.85±0.10	

## 【Temperature Characteristic C6 : X6S(-55~+105°C)】1.25mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLAST21GBC6106□TNA01	TMK212BC6106□G-T	25	X6S	10 μ	±10, ±20	10	150	1.25+0.20/-0	
MLASE21GBC6226MTNC12	EMK212BC6226MG-TT	16	X6S	22 μ	±20	10	150	1.25+0.20/-0	
MLASL21GBC6226MTNA01	LМК212BC6226MG-T	10	X6S	22 μ	±20	10	150	1.25+0.20/-0	
MLASJ21GBC6226MTNA01	JMK212BC6226MG-T	6.3	X6S	22 μ	±20	10	150	1.25+0.20/-0	
MLASA21GAC6226MTNA01	AMK212AC6226MG-T	4	X6S	22 μ	±20	10	150	1.25+0.15/-0.05	
MLASA21GBC6476MTNA01	AMK212BC6476MG-T	4	X6S	47 μ	±20	10	150	1.25+0.20/-0	

## 【Temperature Characteristic C6 : X6S(-55~+105°C)】0.85mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASL219JC6106□TNA01	LМК212AC6106□D-T	10	X6S	10 μ	±10, ±20	10	150	0.85±0.10	
MLASA219LC6226MTNA01	AMK212BC6226MD-T	4	X6S	22 μ	±20	10	150	0.85±0.10	

## 【Temperature Characteristic B7 : X7R(-55~+125°C)】1.25mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU21GSB7224□TNA01	UMK212 B7224□G-T	50	X7R	0.22 μ	±10, ±20	3.5	150	1.25±0.10	
MLASU21GSB7474□TNA01	UMK212 B7474□G-T	50	X7R	0.47 μ	±10, ±20	3.5	150	1.25±0.10	
MLASU21GSB7105□TNA01	UMK212 B7105□G-T	50	X7R	1 μ	±10, ±20	10	150	1.25±0.10	
MLASU21GGB7225□TNA01	UMK212BB7225□G-T	50	X7R	2.2 μ	±10, ±20	10	150	1.25+0.20/-0	
MLASG21GSB7105□TNA01	GMK212 B7105□G-T	35	X7R	1 μ	±10, ±20	10	150	1.25±0.10	
MLAST21GSB7225□TNB25	TMK212 B7225□G-TR	25	X7R	2.2 μ	±10, ±20	10	150	1.25±0.10	
MLAST21GAB7475□TNA01	TMK212AB7475□G-T	25	X7R	4.7 μ	±10, ±20	10	150	1.25+0.15/-0.05	
MLASE21GSB7475□TNA01	EMK212 B7475□G-T	16	X7R	4.7 μ	±10, ±20	10	150	1.25±0.10	
MLASE21GGB7106MTNA01	EMK212BB7106MG-T	16	X7R	10 μ	±20	10	150	1.25+0.20/-0	
MLASL21GAB7106□TNA01	LМК212AB7106□G-T	10	X7R	10 μ	±10, ±20	10	150	1.25+0.15/-0.05	
MLASJ21GAB7106□TNA01	JMK212AB7106□G-T	6.3	X7R	10 μ	±10, ±20	10	150	1.25+0.15/-0.05	

## 【Temperature Characteristic B7 : X7R(-55~+125°C)】0.85mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU219JB7104□TNA01	UMK212AB7104□D-T	50	X7R	0.1 μ	±10, ±20	10	150	0.85±0.10	
MLASU219JB7224□TNA01	UMK212AB7224□D-T	50	X7R	0.22 μ	±10, ±20	10	150	0.85±0.10	
MLASU219JB7474□TNA01	UMK212AB7474□D-T	50	X7R	0.47 μ	±10, ±20	10	150	0.85±0.10	
MLASU219JB7105□TNA01	UMK212AB7105□D-T	50	X7R	1 μ	±10, ±20	10	150	0.85±0.10	
MLAST219JB7225□TNB25	TMK212AB7225□D-TR	25	X7R	2.2 μ	±10, ±20	10	150	0.85±0.10	
MLASE219SB7474□TNA01	EMK212 B7474□D-T	16	X7R	0.47 μ	±10, ±20	3.5	200	0.85±0.10	
MLASE219SB7105□TNA01	EMK212 B7105□D-T	16	X7R	1 μ	±10, ±20	5	200	0.85±0.10	
MLASE219JB7225□TNA01	EMK212AB7225□D-T	16	X7R	2.2 μ	±10, ±20	5	150	0.85±0.10	
MLASE219LB7475MTNA01	EMK212BB7475MD-T	16	X7R	4.7 μ	±20	10	150	0.85±0.10	
MLASL219SB7105□TNA01	LМК212 B7105□D-T	10	X7R	1 μ	±10, ±20	3.5	200	0.85±0.10	
MLASL219JB7225□TNA01	LМК212AB7225□D-T	10	X7R	2.2 μ	±10, ±20	5	200	0.85±0.10	
MLASL219JB7475□TNB25	LМК212AB7475□D-TR	10	X7R	4.7 μ	±10, ±20	10	150	0.85±0.10	

## PARTS NUMBER

## 3216TYPE

【Temperature Characteristic B5(BJ): X5R(-55~+85°C)】 1.6mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU31LSB5475□TNA01	UMK316 BJ475□L-T	50	X5R	4.7 μ	±10, ±20	10	150	1.6±0.20	
MLASU31LBB5106□TNA01	UMK316BBJ106□L-T	50	X5R	10 μ	±10, ±20	10	150	1.6±0.30	
MLAST31LBB5226MTNA01	TMK316BBJ226ML-T	25	X5R	22 μ	±20	10	150	1.6±0.30	
MLASE31LBB5476MTNA01	EMK316BBJ476ML-T	16	X5R	47 μ	±20	10	150	1.6±0.30	
MLASL31LAB5476MTNA01	LMK316ABJ476ML-T	10	X5R	47 μ	±20	10	150	1.6±0.20	
MLASJ31LAB5107MTNA01	JMK316ABJ107ML-T	6.3	X5R	100 μ	±20	10	150	1.6±0.20	
MLASA31LAB5107MTNA01	AMK316ABJ107ML-T	4	X5R	100 μ	±20	10	150	1.6±0.20	
MLASA31LBB5157MTNA01	AMK316BBJ157ML-T	4	X5R	150 μ	±20	10	150	1.6±0.30	
MLASP31LBB5227MTNA01	PMK316BBJ227ML-T	2.5	X5R	220 μ	±20	10	150	1.6±0.30	

【Temperature Characteristic B5(BJ): B(-25~+85°C)/X5R(-55~+85°C)】 0.85mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU319HB5105□TNA01	UMK316 BJ105□D-T	50	B X5R	1 μ	±10, ±20	3.5	150	0.85±0.10	
MLASU319HB5225□TNA01	UMK316 BJ225□D-T	50	B X5R	2.2 μ	±10, ±20	3.5	150	0.85±0.10	
MLASU319LB5475□TNA01	UMK316ABJ475□D-T	50	X5R	4.7 μ	±10, ±20	10	150	0.85±0.10	
MLAST319HB5105□TNA01	TMK316 BJ105□D-T	25	B X5R	1 μ	±10, ±20	3.5	200	0.85±0.10	
MLAST319HB5225□TNA01	TMK316 BJ225□D-T	25	B X5R	2.2 μ	±10, ±20	3.5	150	0.85±0.10	
MLAST319HB5475□TNA01	TMK316 BJ475□D-T	25	X5R	4.7 μ	±10, ±20	5	150	0.85±0.10	
MLAST319LB5106□TNA01	TMK316ABJ106□D-T	25	X5R	10 μ	±10, ±20	10	150	0.85±0.10	
MLASE319HB5225□TNA01	EMK316 BJ225□D-T	16	B X5R	2.2 μ	±10, ±20	3.5	200	0.85±0.10	
MLASE319HB5475□TNA01	EMK316 BJ475□D-T	16	B X5R	4.7 μ	±10, ±20	5	200	0.85±0.10	
MLASE319HB5106□TNA01	EMK316 BJ106□D-T	16	X5R	10 μ	±10, ±20	10	150	0.85±0.10	
MLASE319LB5226MTNA01	EMK316ABJ226MD-T	16	X5R	22 μ	±20	10	150	0.85±0.10	
MLASL319HB5475□TNA01	LMK316 BJ475□D-T	10	B X5R	4.7 μ	±10, ±20	5	200	0.85±0.10	
MLASL319HB5106□TNA01	LMK316 BJ106□D-T	10	X5R	10 μ	±10, ±20	10	200	0.85±0.10	
MLASL319LB5226MTNA01	LMK316ABJ226MD-T	10	X5R	22 μ	±20	10	150	0.85±0.10	
MLASJ319HB5106□TNA01	JMK316 BJ106□D-T	6.3	X5R	10 μ	±10, ±20	10	200	0.85±0.10	
MLASJ319LB5226MTNA01	JMK316ABJ226MD-T	6.3	X5R	22 μ	±20	10	150	0.85±0.10	
MLASJ319LB5476MTNA01	JMK316ABJ476MD-T	6.3	X5R	47 μ	±20	10	150	0.85±0.10	

【Temperature Characteristic C6 : X6S(-55~+105°C)】 1.6mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASE31LBC6226MTNA01	EMK316BC6226ML-T	16	X6S	22 μ	±20	10	150	1.6±0.30	
MLASL31LBC6476MTNA01	LMK316BC6476ML-T	10	X6S	47 μ	±20	10	150	1.6±0.30	
MLASJ31LAC6476MTNA01	JMK316AC6476ML-T	6.3	X6S	47 μ	±20	10	150	1.6±0.20	
MLASA31LAC6476MTNA01	AMK316AC6476ML-T	4	X6S	47 μ	±20	10	200	1.6±0.20	
MLASA31LAC6107MTNA01	AMK316AC6107ML-T	4	X6S	100 μ	±20	10	150	1.6±0.20	

【Temperature Characteristic C7 : X7S(-55~+125°C)】 1.6mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASJ31LAC7476MTNA01	JMK316AC7476ML-T	6.3	X7S	47 μ	±20	10	150	1.6±0.20	
MLASA31LAC7476MTNA01	AMK316AC7476ML-T	4	X7S	47 μ	±20	10	150	1.6±0.20	

【Temperature Characteristic B7 : X7R(-55~+125°C)】 1.6mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU31LSB7225□TNA01	UMK316 B7225□L-T	50	X7R	2.2 μ	±10, ±20	10	150	1.6±0.20	
MLASU31LAB7475□TNA01	UMK316AB7475□L-T	50	X7R	4.7 μ	±10, ±20	10	150	1.6±0.20	
MLASG31LAB7106□TNA01	GMK316AB7106□L-TR	35	X7R	10 μ	±10, ±20	10	150	1.6±0.20	
MLAST31LAB7475□TNA01	TMK316AB7475□L-T	25	X7R	4.7 μ	±10, ±20	10	200	1.6±0.20	
MLAST31LAB7106□TNA01	TMK316AB7106□L-T	25	X7R	10 μ	±10, ±20	10	150	1.6±0.20	
MLASE31LSB7475□TNA01	EMK316 B7475□L-T	16	X7R	4.7 μ	±10, ±20	5	200	1.6±0.20	
MLASE31LAB7106□TNA01	EMK316AB7106□L-T	16	X7R	10 μ	±10, ±20	10	200	1.6±0.20	
MLASL31LAB7106□TNA01	LMK316AB7106□L-T	10	X7R	10 μ	±10, ±20	10	200	1.6±0.20	
MLASL31LAB7226□TNA01	LMK316AB7226□L-TR	10	X7R	22 μ	±10, ±20	10	150	1.6±0.20	

【Temperature Characteristic B7 : X7R(-55~+125°C)】 0.85mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU319HB7225□TNA01	UMK316 B7225□D-T	50	X7R	2.2 μ	±10, ±20	10	150	0.85±0.10	
MLAST319LB7475□TNA01	TMK316AB7475□D-T	25	X7R	4.7 μ	±10, ±20	10	150	0.85±0.10	
MLASL319LB7106MTNA01	LMK316AB7106MD-T	10	X7R	10 μ	±20	10	150	0.85±0.10	

## PARTS NUMBER

## 3225TYPE

【Temperature Characteristic B5(BJ): X5R(-55~+85°C)】 2.5mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU32MSB5106[PNA01	UMK325 BJ106[M-P	50	X5R	10 μ	±10, ±20	5	150	2.5±0.20	
MLASG32MSB5226MPNA01	GMK325 BJ226MM-P	35	X5R	22 μ	±20	5	150	2.5±0.20	
MLAST32MAB5476MPNDT1	TMK325ABJ476MM-P	25	X5R	47 μ	±20	10	150	2.5±0.30	
MLASE32MAB5107MPNA01	EMK325ABJ107MM-P	16	X5R	100 μ	±20	10	150	2.5±0.30	
MLASL32MAB5107MPNA01	LMK325ABJ107MM-P	10	X5R	100 μ	±20	10	150	2.5±0.30	
MLASJ32MAB5157MPNDT1	JMK325ABJ157MM-P	6.3	X5R	150 μ	±20	10	150	2.5±0.30	
MLASJ32MAB5227MPNDT1	JMK325ABJ227MM-P	6.3	X5R	220 μ	±20	10	150	2.5±0.30	
MLASA32MAB5157MPNDT1	AMK325ABJ157MM-P	4	X5R	150 μ	±20	10	150	2.5±0.30	
MLASA32MAB5227MPNDT1	AMK325ABJ227MM-P	4	X5R	220 μ	±20	10	150	2.5±0.30	

【Temperature Characteristic B5(BJ): B(-25~+85°C)/X5R(-55~+85°C)】 1.9mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU32NSB5475[TNA01	UMK325 BJ475[N-T	50	X5R	4.7 μ	±10, ±20	10	150	1.9±0.20	
MLASG32NSB5225[TNA01	GMK325 BJ225[N-T	35	B X5R	2.2 μ	±10, ±20	3.5	200	1.9±0.20	
MLASG32NSB5475[TNA01	GMK325 BJ475[N-T	35	X5R	4.7 μ	±10, ±20	10	150	1.9±0.20	
MLASG32NSB5106[TNA01	GMK325 BJ106[N-T	35	X5R	10 μ	±10, ±20	5	150	1.9±0.20	
MLAST32NSB5335MTNA01	TMK325 BJ335MN-T	25	B X5R <sup>*1</sup>	3.3 μ	±20	3.5	200	1.9±0.20	
MLAST32NSB5475[TNA01	TMK325 BJ475[N-T	25	B X5R <sup>*1</sup>	4.7 μ	±10, ±20	3.5	200	1.9±0.20	
MLAST32NSB5106[TNA01	TMK325 BJ106[N-T	25	X5R	10 μ	±10, ±20	5	200	1.9±0.20	
MLASE32NSB5475[TNA01	EMK325 BJ475[N-T	16	B X5R <sup>*1</sup>	4.7 μ	±10, ±20	3.5	200	1.9±0.20	
MLASE32NSB5106[TNA01	EMK325 BJ106[N-T	16	X5R	10 μ	±10, ±20	3.5	200	1.9±0.20	
MLASE32YBB5476MTNA01	EMK325 BJ476MY-T	16	X5R	47 μ	±20	10	150	1.9+0.1/-0.2	
MLASL32NSB5106[TNA01	LMK325 BJ106[N-T	10	X5R	10 μ	±10, ±20	3.5	200	1.9±0.20	
MLASL32YBB5226MTNA01	LMK325 BJ226MY-T	10	B X5R	22 μ	±20	5	150	1.9+0.1/-0.2	
MLASJ32YBB5226MTNA01	JMK325 BJ226MY-T	6.3	B X5R	22 μ	±20	5	200	1.9+0.1/-0.2	

【Temperature Characteristic B5(BJ): B(-25~+85°C)/X5R(-55~+85°C)】 0.85mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLAST32JB5106[TNA01	TMK325 BJ106[D-T	25	X5R	10 μ	±10, ±20	5	150	0.85±0.10	
MLASE32JB5106[TNA01	EMK325 BJ106[D-T	16	X5R	10 μ	±10, ±20	5	150	0.85±0.10	
MLASE32YBB5226MTNA01	EMK325 BJ226MD-T	16	X5R	22 μ	±20	10	150	0.85±0.10	
MLASL32JB5335[TNA01	LMK325 BJ335[D-T	10	B X5R	3.3 μ	±10, ±20	3.5	200	0.85±0.10	
MLASL32JB5475[TNA01	LMK325 BJ475[D-T	10	B X5R	4.7 μ	±10, ±20	5	200	0.85±0.10	
MLASL32JB5106[TNA01	LMK325 BJ106[D-T	10	X5R	10 μ	±10, ±20	5	150	0.85±0.10	

【Temperature Characteristic C6 : X6S(-55~+105°C)】 2.5mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASE32MAC6476MPNDT1	EMK325AC6476MM-P	16	X6S	47 μ	±20	10	150	2.5±0.30	
MLASL32MAC6107MPNA01	LMK325AC6107MM-P	10	X6S	100 μ	±20	10	150	2.5±0.30	
MLASA32MAC6157MPNDT1	AMK325AC6157MM-P	4	X6S	150 μ	±20	10	150	2.5±0.30	
MLASA32MAC6227MPNDT1	AMK325AC6227MM-P	4	X6S	220 μ	±20	10	150	2.5±0.30	
MLASP32MAC6227MPNDT1	PMK325AC6227MM-P	2.5	X6S	220 μ	±20	10	200	2.5±0.30	

【Temperature Characteristic B7 : X7R(-55~+125°C)】 2.5mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU32MSB7335[PNA01	UMK325 B7335[M-P	50	X7R	3.3 μ	±10, ±20	3.5	200	2.5±0.20	
MLASU32MSB7475[PNA01	UMK325 B7475[M-P	50	X7R	4.7 μ	±10, ±20	5	150	2.5±0.20	
MLASU32MAB7106[PNA01	UMK325AB7106[M-P	50	X7R	10 μ	±10, ±20	10	150	2.5±0.30	
MLAST32MAB7106[PNA01	TMK325AB7106[M-P	25	X7R	10 μ	±10, ±20	10	200	2.5±0.30	
MLAST32MSB7226[PNB25	TMK325 B7226[M-PR	25	X7R	22 μ	±10, ±20	10	150	2.5±0.20	
MLASE32MSB7226[PNB25	EMK325 B7226[M-PR	16	X7R	22 μ	±10, ±20	10	150	2.5±0.20	
MLASL32MSB7476[PNB25	LMK325 B7476[M-PR	10	X7R	47 μ	±10, ±20	10	150	2.5±0.20	
MLASJ32MSB7476[PNB25	JMK325 B7476[M-PR	6.3	X7R	47 μ	±10, ±20	10	200	2.5±0.20	

【Temperature Characteristic B7 : X7R(-55~+125°C)】 1.9mm thickness

New part number	Old part number (for reference)	Rated voltage [V]	Temperature characteristics	Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness*3 [mm]	Note
							Rated voltage x %		
MLASU32NSB7475[TNB25	UMK325 B7475[N-TR	50	X7R	4.7 μ	±10, ±20	10	150	1.9±0.20	
MLAST32NSB7335[TNA01	TMK325 B7335[N-T	25	X7R	3.3 μ	±10, ±20	3.5	200	1.9±0.20	
MLAST32NSB7475[TNA01	TMK325 B7475[N-T	25	X7R	4.7 μ	±10, ±20	3.5	150	1.9±0.20	
MLAST32NSB7106[TNB25	TMK325 B7106[N-TR	25	X7R	10 μ	±10, ±20	10	150	1.9±0.20	
MLASE32NSB7475[TNA01	EMK325 B7475[N-T	16	X7R	4.7 μ	±10, ±20	3.5	200	1.9±0.20	
MLASE32NSB7106[TNA01	EMK325 B7106[N-T	16	X7R	10 μ	±10, ±20	3.5	150	1.9±0.20	
MLASL32NSB7106[TNA01	LMK325 B7106[N-T	10	X7R	10 μ	±10, ±20	3.5	200	1.9±0.20	



# Multilayer Ceramic Capacitors

## PACKAGING

### ① Minimum Quantity

#### ● Taped package

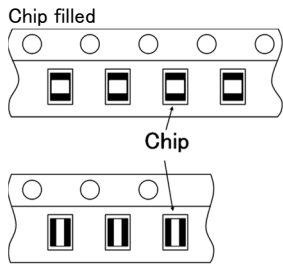
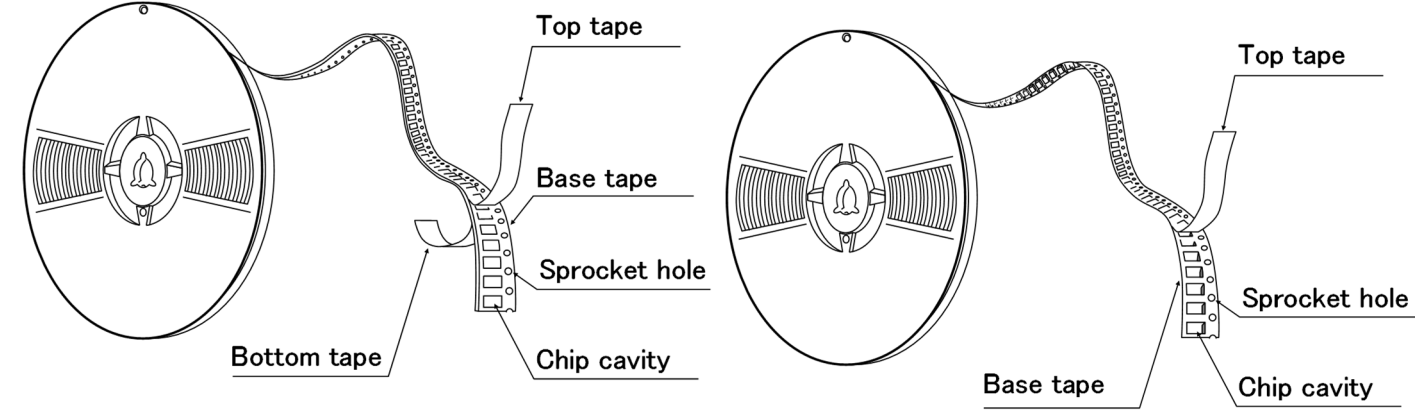
Type			Thickness		Standard Quantity [pcs]	
Code	JIS(mm)	EIA(inch)	[mm]	Code	Paper tape	Embossed tape
02	0201	008004	0.125	1	—	50000
04	0402	01005	0.2	2	—	40000
06	0603	0201	0.3	3	15000	—
1L	1005	0402	0.13	H	—	20000
			0.18	E	—	15000
			0.2	2	20000	—
			0.3	3	15000	—
10	1005	0402	0.5	5	10000	—
	0510 ※	0204	0.3	3	10000	—
16	1608	0603	0.45	K	4000	—
			0.7	7		
			0.8	8		
			0.8	8	3000 (Soft Termination)	3000 (Soft Termination)
	0816 ※	0306	0.5	5	—	4000
21	2012	0805	0.85	9	4000	—
			1.25	G	—	3000
			1.25	G	—	2000 (Soft Termination)
	1220 ※	0508	0.85	9	4000	—
31	3216	1206	0.85	9	4000	—
			1.15	Q	—	3000
			1.6	L	—	2000
32	3225	1210	0.85	9	—	2000
			1.15	Q		
			1.9	N		
			2.0 max	Y		
			2.5	M	—	500(T), 1000(P)
45	4532	1812	2.0 max	Y	—	1000
			2.5	M	—	500

注: ※LW Reverse type (MSRL, MCRL, MBRL, MLRL, MMRL)

## ② Taping material

※ No bottom tape for pressed carrier tape

- Card board carrier tape
- Embossed tape

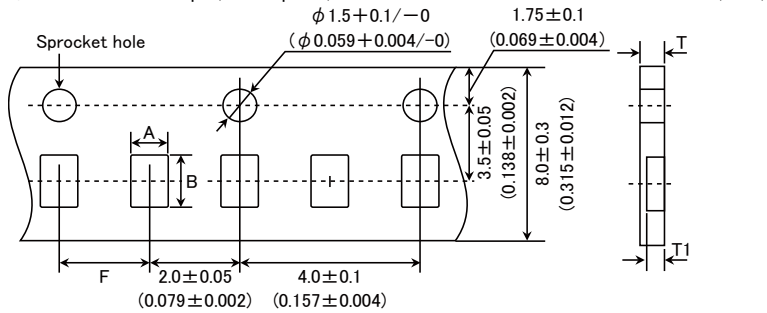


※ LW Reverse type.

## ③ Representative taping dimensions

● Paper Tape (8mm wide)

● Pressed carrier tape ( 2mm pitch)

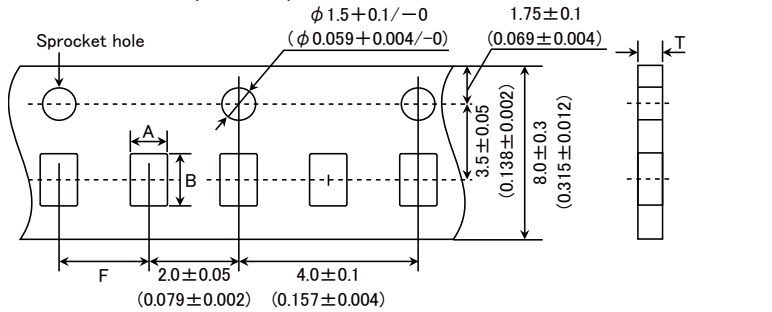


Type(EIA)	Chip Cavity		Insertion Pitch F	Tape Thickness	
	A	B		T	T1
0603 (0201)	0.37	0.67	2.0±0.05	0.45max.	0.42max.
0510 (0204) ※	0.65	1.15		0.4max.	0.3max.
1005 (0402) (*1 2)				0.45max.	0.42max.
1005 (0402) (*1 3)					

Note \*1 Thickness, 2:0.2mm, 3:0.3mm. ※ LW Reverse type.

Unit: mm

● Punched carrier tape (2mm pitch)

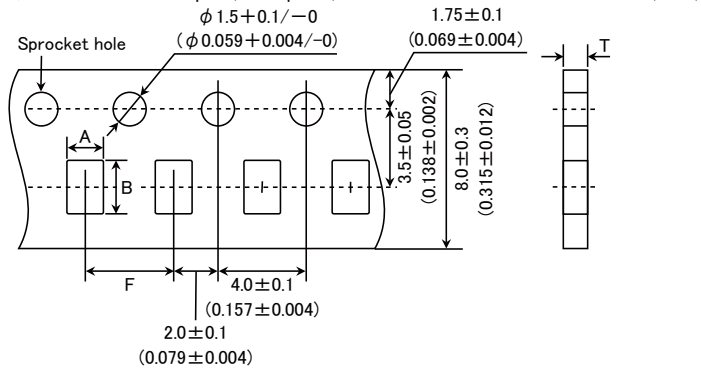


Type(EIA)	Chip Cavity		Insertion Pitch F	Tape Thickness
	A	B		T
1005 (0402)	0.65	1.15	2.0±0.05	0.8max.

Unit: mm

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● Punched carrier tape (4mm pitch)

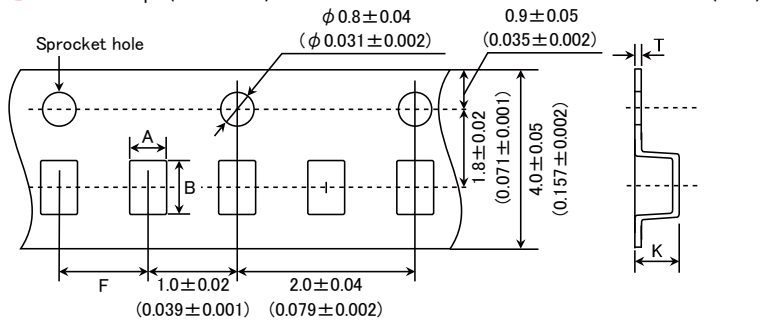


Type(EIA)	Chip Cavity		Insertion Pitch F	Tape Thickness	
	A	B		K	T
1608 (0603)	1.0	1.8	4.0±0.1	1.1max.	1.1max.
0816 (0306) ※					
2012 (0805)					
1220 (0508) ※	1.65	2.4	4.0±0.1	1.1max.	1.1max.
3216 (1206)	2.0	3.6			

Note: Taping size might be different depending on the size of the product. ※ LW Reverse type.

Unit: mm

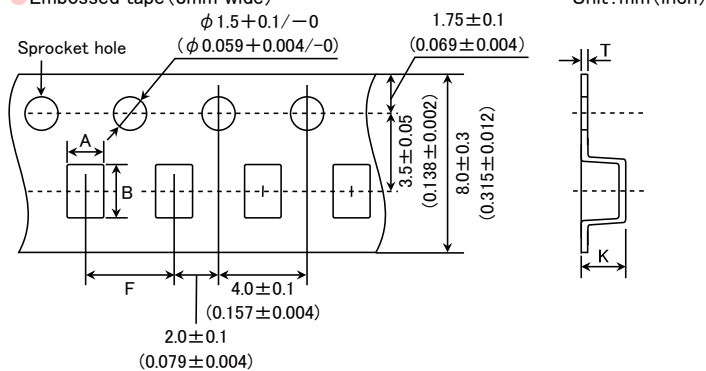
● Embossed tape (4mm wide)



Type(EIA)	Chip Cavity		Insertion Pitch F	Tape Thickness	
	A	B		K	T
0201 (008004)	0.135	0.27	1.0±0.02	0.5max.	0.25max.
0402 (01005)					

Unit: mm

● Embossed tape (8mm wide)



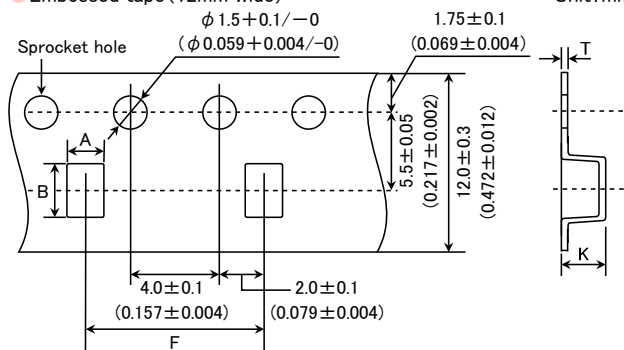
Type(EIA)	Chip Cavity		Insertion Pitch F	Tape Thickness	
	A	B		K	T
1005 (0402)	1.0	1.8	2.0±0.1	0.6max	0.2±0.1
0816 (0306) ※					
2012 (0805)			4.0±0.1	1.3max.	0.25±0.1
3216 (1206)					
3225 (1210)					
0816 (0306) ※	1.65	2.4	3.4max.	0.6max.	
3216 (1206)	2.0	3.6			

Note: ※ LW Reverse type.

Unit: mm

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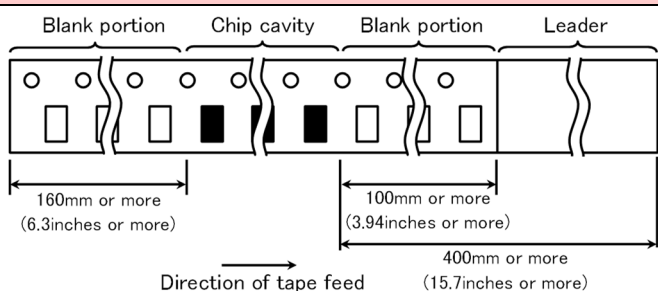
● Embossed tape (12mm wide) Unit: mm (inch)



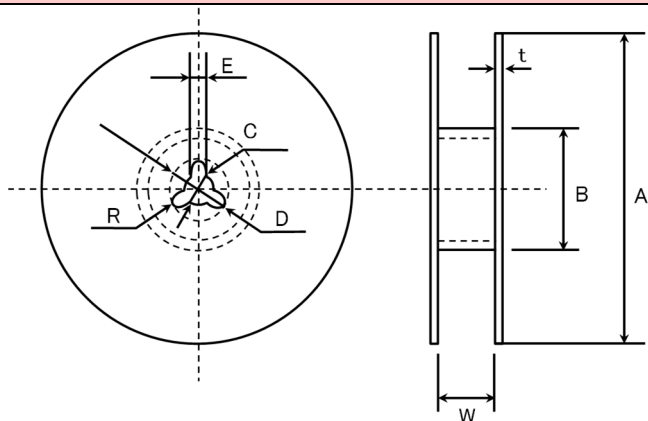
Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B		K	T
3225 (1210)	3.1	4.0	8.0 ± 0.1	4.0max.	0.6max.
4532 (1812)	3.7	4.9	8.0 ± 0.1	4.0max.	0.6max.

Unit: mm

④ Trailer and Leader



⑤ Reel size



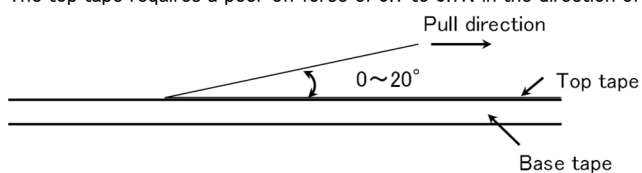
A	B	C	D	E	R
$\phi 178 \pm 2.0$	$\phi 50 \text{min.}$	$\phi 13.0 \pm 0.2$	$\phi 21.0 \pm 0.8$	$2.0 \pm 0.5$	1.0

	T	W
4mm wide tape	1.5max.	$5 \pm 1.0$
8mm wide tape	2.5max.	$10 \pm 1.5$
12mm wide tape	2.5max.	$14 \pm 1.5$

Unit: mm

⑥ Top Tape Strength

The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.



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**Multilayer Ceramic Capacitors for General Electronic Equipment for Consumer**  
**Multilayer Ceramic Capacitors**  
**for Medical Devices classified as GHTF Classes A or B (Japan Classes I or II)**

■ RELIABILITY DATA

1. Operating Temperature Range

Specified Value	Temperature Compensating (Class1)	Standard	-55 to +125°C	
		High Frequency Type		
Specified Value	High Permittivity (Class2)		Specification	Temperature Range
		B5	B	-25 to +85°C
			X5R	-55 to +85°C
		B7	X7R	-55 to +125°C
		C6	X6S	-55 to +105°C
C7	X7S	-55 to +125°C		

2. Storage Conditions

Specified Value	Temperature Compensating (Class1)	Standard	-55 to +125°C	
		High Frequency Type		
Specified Value	High Permittivity (Class2)		Specification	Temperature Range
		B5	B	-25 to +85°C
			X5R	-55 to +85°C
		B7	X7R	-55 to +125°C
		C6	X6S	-55 to +105°C
C7	X7S	-55 to +125°C		

3. Rated Voltage

Specified Value	Temperature Compensating (Class1)	Standard	50VDC, 25VDC, 16VDC
		High Frequency Type	25VDC, 16VDC
	High Permittivity (Class2)		50VDC, 35VDC, 25VDC, 16VDC, 10VDC, 6.3VDC, 4VDC, 2.5VDC

4. Withstanding Voltage (Between terminals)

Specified Value	Temperature Compensating (Class1)	Standard	No breakdown or damage
		High Frequency Type	
Test Methods and Remarks	High Permittivity (Class2)		
		Class 1	Class 2
	Applied voltage	Rated voltage × 3	Rated voltage × 2.5
	Duration	1 to 5 sec.	
	Charge/discharge current	50mA max.	

5. Insulation Resistance

Specified Value	Temperature Compensating (Class1)	Standard	10000 MΩ min.
		High Frequency Type	
Test Methods and Remarks	High Permittivity (Class2) Note 1		$C \leq 0.047 \mu F$ : 10000 MΩ min.
			$C > 0.047 \mu F$ : $500 M\Omega \cdot \mu F$ (C: Nominal capacitance)
	Applied voltage	: Rated voltage	
Duration	: 60 ± 5 sec.		
Charge/discharge current	: 50mA max.		

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**6. Capacitance (Tolerance)**

Specified Value	Temperature Compensating (Class1)	Standard	$0.2\text{pF} \leq C \leq 5\text{pF} : \pm 0.25\text{pF}$ $5\text{pF} \leq C \leq 10\text{pF} : \pm 0.5\text{pF}$ $C > 10\text{pF} : \pm 5\%$		
		High Frequency Type	Refer to detailed specification		
	High Permittivity (Class2)		$\pm 10\%$ or $\pm 20\%$		
Test Methods and Remarks		Class 1		Class 2	
		Standard	High Frequency Type	$C \leq 10 \mu\text{F}$	$C > 10 \mu\text{F}$
	Preconditioning	None		Thermal treatment (at 150°C for 1hr) Note 2	
	Measuring frequency	1MHz $\pm$ 10%	1GHz	1kHz $\pm$ 10%	120 $\pm$ 10Hz
	Measuring voltage Note 1	0.5 to 5Vrms		1 $\pm$ 0.2Vrms	0.5 $\pm$ 0.1Vrms
	Bias application	None			

**7. Q or Dissipation Factor**

Specified Value	Temperature Compensating (Class1)	Standard	$C < 30\text{pF} : Q \geq 400 + 20C$ $C \geq 30\text{pF} : Q \geq 1000$ (C: Nominal capacitance)		
		High Frequency Type	Refer to detailed specification		
	High Permittivity (Class2) Note 1		2.5% max.		
Test Methods and Remarks		Class 1		Class 2	
		Standard	High Frequency Type	$C \leq 10 \mu\text{F}$	$C > 10 \mu\text{F}$
	Preconditioning	None		Thermal treatment (at 150°C for 1hr) Note 2	
	Measuring frequency	1MHz $\pm$ 10%	1GHz	1kHz $\pm$ 10%	120 $\pm$ 10Hz
	Measuring voltage Note 1	0.5 to 5Vrms		1 $\pm$ 0.2Vrms	0.5 $\pm$ 0.1Vrms
	Bias application	None			

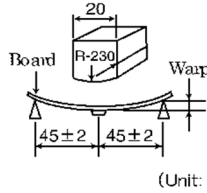
**8. Temperature Characteristic (Without voltage application)**

Specified Value	Temperature Compensating (Class1)	Standard	Temperature Characteristic [ppm/°C]		Tolerance [ppm/°C]		
			$C \square : 0$	CG(C0G) CH(C0H) CJ(C0J) CK(C0K)	G: $\pm 30$ H: $\pm 60$ J: $\pm 120$ H: $\pm 250$		
		High Frequency Type	Temperature Characteristic [ppm/°C]		Tolerance [ppm/°C]		
			$C \square : 0$	CG(C0G) CH(C0H)	G: $\pm 30$ H: $\pm 60$		
	High Permittivity (Class2)			Specification	Capacitance change	Reference temperature	Temperature Range
			B5	B X5R	$\pm 10\%$ $\pm 15\%$	20°C 25°C	-25 to +85°C -55 to +85°C
			B7	X7R	$\pm 15\%$	25°C	-55 to +125°C
			C6	XS	$\pm 22\%$	25°C	-55 to +105°C
			C7	X7S	$\pm 22\%$	25°C	-55 to +125°C

Test Methods and Remarks	Class 1 Capacitance at 20°C and 85°C shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.				
	$\frac{(C_{85} - C_{20})}{C_{20} \times \Delta T} \times 10^6 (\text{ppm}/^\circ\text{C}) \quad \Delta T = 65$				
	Class 2 Capacitance at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.				
	Step	B	X5R, X7R, X6S, X7S		
	1	Minimum operating temperature			
2	20°C	25°C			
3	Maximum operating temperature				
	$\frac{(C - C_2)}{C_2} \times 100 (\%) \quad C : \text{Capacitance in Step 1 or Step 3}$ $C_2 : \text{Capacitance in Step 2}$				
	※Measuring frequency and voltage: Refer to detailed specification				

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## 9. Deflection

Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality Capacitance change : Within $\pm 5\%$ or $\pm 0.5$ pF, whichever is larger.	
		High Frequency Type	Appearance : No abnormality Capacitance change : Within $\pm 0.5$ pF	
	High Permittivity (Class2)		Appearance : No abnormality Capacitance change : Within $\pm 12.5\%$	
Test Methods and Remarks	Multilayer Ceramic Capacitors		 <p>(Unit: mm) Capacitance measurement shall be conducted with the board bent</p>	
		0201, 0402, 0603, ※1005 Type		
		The other types		
	Board	Glass epoxy-resin substrate		
	Thickness	0.8mm		1.6mm
	Warp	1mm		
	Duration	10 sec.		
※1005 Type thickness, 2: 0.2mm, 3: 0.3mm.				

## 10. Adhesive Strength of Terminal Electrodes

Specified Value	Temperature Compensating (Class1)	Standard	No terminal separation or its indication.	
		High Frequency Type		
	High Permittivity (Class2)			
Test Methods and Remarks		0201Type	0402, 0603Type	1005Type or more
	Applied force	1N	2N	5N
	Duration	10 ± 1 sec		30 ± 5 sec

## 11. Vibration

Specified Value	Temperature Compensating (Class1)	Standard	Initial performance shall be satisfied.
		High Frequency Type	
	High Permittivity (Class2)		
Test Methods and Remarks	Preconditioning	: Thermal treatment (at 150°C for 1hr) Note2 (Only High permittivity)	
	Frequency range	: 10 to 55 Hz	
	Overall amplitude	: 1.5 mm	
	Sweeping method	: 10 to 55 to 10 Hz for 1 min Two hours each in X, Y, Z directions: 6 hrs in total	

## 12. Solderability

Specified Value	Temperature Compensating (Class1)	Standard	At least 95% of terminal electrode is covered by new solder.
		High Frequency Type	
	High Permittivity (Class2)		
Test Methods and Remarks		Eutectic solder	Lead-free solder
	Solder type	H60A or H63A	Sn-3.0Ag-0.5Cu
	Solder temperature	230 ± 5°C	
	Duration	4 ± 1 sec.	

### 13. Resistance to Soldering

Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality Capacitance change : Within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ , whichever is larger. Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality	
		High Frequency Type	Appearance : No abnormality Capacitance change : Within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ , whichever is larger. Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality	
	High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within $\pm 7.5\%$ Dissipation factor : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality	
Test Methods and Remarks	Class 1			
		0201, 0402, 0603 Type	1005 Type	
	Preconditioning	None		
	Preheating	150°C, 1 to 2 min.	80 to 100°C, 2 to 5 min. 150 to 200°C, 2 to 5 min.	
	Solder temp.	270 $\pm$ 5°C		
	Duration	3 $\pm$ 0.5 sec.		
	Recovery	24 $\pm$ 2 hrs (Standard condition) Note 5		
	Class 2			
		0201, 0402, 0603 Type	1005, 1608, 2012 Type	3216, 3225, 4532 Type
	Preconditioning	Thermal treatment (at 150°C for 1 hr) Note 2		
	Preheating	150°C, 1 to 2 min.	80 to 100°C, 2 to 5 min. 150 to 200°C, 2 to 5 min.	80 to 100°C, 5 to 10 min. 150 to 200°C, 5 to 10 min.
	Solder temp.	270 $\pm$ 5°C		
	Duration	3 $\pm$ 0.5 sec.		
	Recovery	24 $\pm$ 2 hrs (Standard condition) Note 5		

### 14. Temperature Cycle (Thermal Shock)

Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality Capacitance change : Within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ , whichever is larger. Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality	
		High Frequency Type	Appearance : No abnormality Capacitance change : Within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ , whichever is larger. Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality	
	High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within $\pm 7.5\%$ Dissipation factor : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality	
Test Methods and Remarks	Class 1		Class 2	
	Preconditioning	None	Thermal treatment (at 150°C for 1 hr) Note 2	
	1 cycle	Step	Temperature (°C)	Time (min.)
		1	Minimum operating temperature	30 $\pm$ 3
		2	Normal temperature	2 to 3
		3	Maximum operating temperature	30 $\pm$ 3
	4	Normal temperature	2 to 3	
Number of cycles	5 times			
Recovery	24 $\pm$ 2 hrs (Standard condition) Note 5			

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15. Humidity (Steady State)			
Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality Capacitance change : Within $\pm 5\%$ or $\pm 0.5\text{pF}$ , whichever is larger. Q : $C < 10\text{pF} : Q \geq 200 + 10C$ $10 \leq C < 30\text{pF} : Q \geq 275 + 2.5C$ $C \geq 30\text{pF} : Q \geq 350$ (C: Nominal capacitance) Insulation resistance : 1000 M $\Omega$ min.
		High Frequency Type	Appearance : No abnormality Capacitance change : Within $\pm 5\%$ or $\pm 0.5\text{pF}$ , whichever is larger. Insulation resistance : 1000 M $\Omega$ min.
	High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within $\pm 12.5\%$ Dissipation factor : 5.0% max. Insulation resistance : 50 M $\Omega$ $\mu\text{F}$ or 1000 M $\Omega$ whichever is smaller.
Test Methods and Remarks	Preconditioning : Thermal treatment (at 150°C for 1hr) Note2 (Only High permittivity) Temperature : $40 \pm 2^\circ\text{C}$ Humidity : 90 to 95%RH Duration : 500 +24/−0 hrs Recovery : $24 \pm 2$ hrs under the standard condition Note 1,5		

16. Humidity Loading			
Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality Capacitance change : Within $\pm 7.5\%$ or $\pm 0.75\text{pF}$ , whichever is larger. Q : $C < 30\text{pF} : Q \geq 100 + 10C/3$ $C \geq 30\text{pF} : Q \geq 200$ (C: Nominal capacitance) Insulation resistance : 500 M $\Omega$ min.
		High Frequency Type	Appearance : No abnormality Capacitance change : $C \leq 2\text{pF} : \text{Within } \pm 0.4 \text{ pF}$ $C > 2\text{pF} : \text{Within } \pm 0.75 \text{ pF}$ $C > 10\text{pF} : \text{Within } \pm 0.75\%$ (C: Nominal capacitance) Insulation resistance : 500 M $\Omega$ min.
	High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within $\pm 12.5\%$ Dissipation factor : 5.0% max. Insulation resistance : 25 M $\Omega$ $\mu\text{F}$ or 500 M $\Omega$ , whichever is smaller.
Test Methods and Remarks	Preconditioning : Voltage treatment (Rated voltage are applied for 1 hour at 40°C) Note 1,3 (Only High permittivity) Temperature : $40 \pm 2^\circ\text{C}$ Humidity : 90 to 95%RH Duration : 500 +24/−0 hrs Applied voltage : Rated voltage Charge/discharge current : 50mA max. Recovery : $24 \pm 2$ hrs under the standard condition Note 1,5		

## 17. High Temperature Loading

Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality Capacitance change : Within $\pm 3\%$ or $\pm 0.3\text{pF}$ , whichever is larger. Q : $C < 10\text{pF}$ : $Q \geq 200 + 10C$ $10 \leq C < 30\text{pF}$ : $Q \geq 275 + 2.5C$ $C \geq 30\text{pF}$ : $Q \geq 350$ (C: Nominal capacitance) Insulation resistance : $1000 \text{ M}\Omega$ min.
		High Frequency Type	Appearance : No abnormality Capacitance change : Within $\pm 3\%$ or $\pm 0.3\text{pF}$ , whichever is larger. Insulation resistance : $1000 \text{ M}\Omega$ min.
	High Permittivity (Class2) Note 1	Appearance : No abnormality Capacitance change : Within $\pm 12.5\%$ Dissipation factor : $5.0\%$ max. Insulation resistance : $50 \text{ M}\Omega \mu\text{F}$ or $1000 \text{ M}\Omega$ , whichever is smaller.	
Test Methods and Remarks	Preconditioning : Voltage treatment (Twice the rated voltage shall be applied for 1 hour at $85^\circ\text{C}$ , $105^\circ\text{C}$ or $125^\circ\text{C}$ ) Note 1,3,4 (Only High permittivity) Temperature : Maximum operating temperature Duration : $1000 +24/-0$ hrs Applied voltage : Rated voltage $\times 2$ Note 4 Charge/discharge current : $50\text{mA}$ max. Recovery : $24 \pm 2$ hrs under the standard condition Note 1,5		

Note 1 The figures indicate typical specifications. Please refer to individual specifications in detail.

Note 2 Thermal treatment : Initial value shall be measured after test sample is heat-treated at  $150 \pm 0/-10^\circ\text{C}$  for an hour and kept at room temperature for  $24 \pm 2$  hours.

Note 3 Voltage treatment : Initial value shall be measured after test sample is voltage-treated for an hour at both the temperature and voltage specified in the test conditions, and kept at room temperature for  $24 \pm 2$  hours.

Note 4 150% of rated voltage is applicable to some items. Please refer to their specifications for further information.

Note 5 Standard condition: Temperature:  $5$  to  $35^\circ\text{C}$ , Relative humidity:  $45$  to  $85\%$  RH, Air pressure:  $86$  to  $106\text{kPa}$  When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.

Temperature:  $20 \pm 2^\circ\text{C}$ , Relative humidity:  $60$  to  $70\%$  RH, Air pressure:  $86$  to  $106\text{kPa}$  Unless otherwise specified, all the tests are conducted under the "standard condition".

# Multilayer Ceramic Capacitors

## PRECAUTIONS

### 1. Circuit Design

- Precautions**
- ◆ Verification of operating environment, electrical rating and performance
    1. A malfunction of equipment in fields such as medical, aerospace, nuclear control, etc. may cause serious harm to human life or have severe social ramifications. Therefore, any capacitors to be used in such equipment may require higher safety and reliability, and shall be clearly differentiated from them used in general purpose applications.
  - ◆ Operating Voltage (Verification of Rated voltage)
    1. The operating voltage for capacitors must always be their rated voltage or less.
      - If an AC voltage is loaded on a DC voltage, the sum of the two peak voltages shall be the rated voltage or less.
      - For a circuit where an AC or a pulse voltage may be used, the sum of their peak voltages shall also be the rated voltage or less.
    2. Even if an applied voltage is the rated voltage or less reliability of capacitors may be deteriorated in case that either a high frequency AC voltage or a pulse voltage having rapid rise time is used in a circuit.

### 2. PCB Design

- Precautions**
- ◆ Pattern configurations (Design of Land-patterns)
    1. When capacitors are mounted on PCBs, the amount of solder used (size of fillet) can directly affect the capacitor performance. Therefore, the following items must be carefully considered in the design of land patterns:
      - (1) Excessive solder applied can cause mechanical stresses which lead to chip breaking or cracking. Therefore, please consider appropriate land-patterns for proper amount of solder.
      - (2) When more than one component are jointly soldered onto the same land, each component's soldering point shall be separated by solder-resist.
  - ◆ Pattern configurations (Capacitor layout on PCBs)
 

After capacitors are mounted on boards, they can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering of the boards, etc.). For this reason, land pattern configurations and positions of capacitors shall be carefully considered to minimize stresses.

**Technical considerations**

- ◆ Pattern configurations (Design of Land-patterns)
 

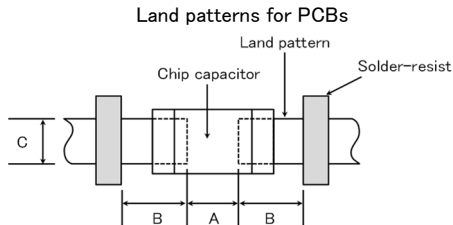
The following diagrams and tables show some examples of recommended land patterns to prevent excessive solder amounts.

(1) Recommended land dimensions for typical chip capacitors

  - Multilayer Ceramic Capacitors : Recommended land dimensions (unit: mm)

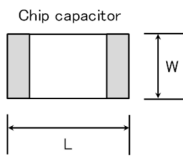
**Wave-soldering**

Type	1608	2012	3216	3225	
Size	L	1.6	2.0	3.2	3.2
	W	0.8	1.25	1.6	2.5
A	0.8 to 1.0	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5	
B	0.5 to 0.8	0.8 to 1.5	0.8 to 1.7	0.8 to 1.7	
C	0.6 to 0.8	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5	



**Reflow-soldering**

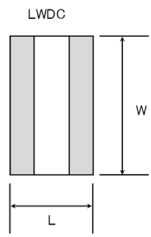
Type	0201	0402	0603	1005	1608	2012	3216	3225	4532
Size	L	0.25	0.4	0.6	1.0	1.6	2.0	3.2	4.5
	W	0.125	0.2	0.3	0.5	0.8	1.25	1.6	3.2
A	0.095~0.135	0.15~0.25	0.20~0.30	0.45~0.55	0.6~0.8	0.8~1.2	1.8~2.5	1.8~2.5	2.5~3.5
B	0.085~0.125	0.10~0.20	0.20~0.30	0.40~0.50	0.6~0.8	0.8~1.2	1.0~1.5	1.0~1.5	1.5~1.8
C	0.110~0.150	0.15~0.30	0.25~0.40	0.45~0.55	0.6~0.8	0.9~1.6	1.2~2.0	1.8~3.2	2.3~3.5



Note: Recommended land size might be different according to the allowance of the size of the product.

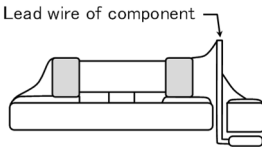
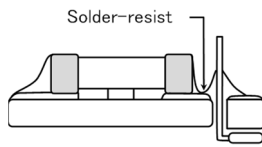
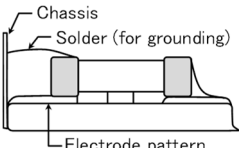
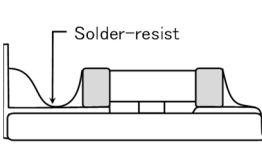
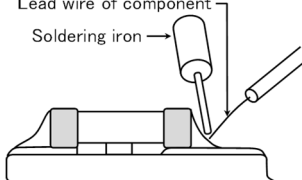
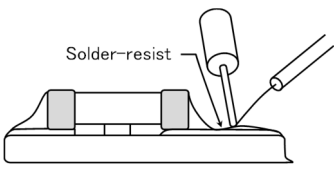
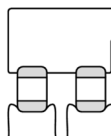
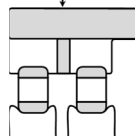
  - LWDC: Recommended land dimensions for reflow-soldering (unit: mm)

Type	0510	0816	1220	
Size	L	0.52	0.8	1.25
	W	1.0	1.6	2.0
A	0.18~0.22	0.25~0.3	0.5~0.7	
B	0.2~0.25	0.3~0.4	0.4~0.5	
C	0.9~1.1	1.5~1.7	1.9~2.1	



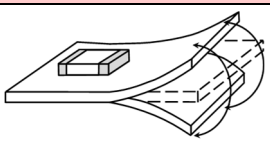
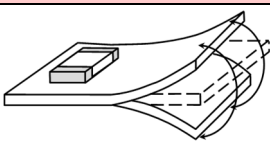
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(2) Examples of good and bad solder application

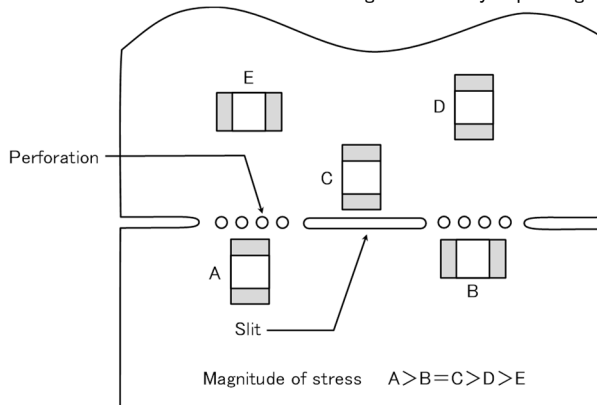
Item	Not recommended	Recommended
Mixed mounting of SMD and leaded components		
Component placement close to the chassis		
Hand-soldering of leaded components near mounted components		
Horizontal component placement		

◆ Pattern configurations (Capacitor layout on PCBs)

1-1. The following is examples of good and bad capacitor layouts ; capacitors shall be located to minimize any possible mechanical stresses from board warp or deflection.

Items	Not recommended	Recommended
Deflection of board		 Place the product at a right angle to the direction of the anticipated mechanical stress.

1-2. The amount of mechanical stresses given will vary depending on capacitor layout. Please refer to diagram below.



1-3. When PCB is split, the amount of mechanical stress on the capacitors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, please consider the PCB, split methods as well as chip location.

3. Mounting

Precautions

◆ Adjustment of mounting machine

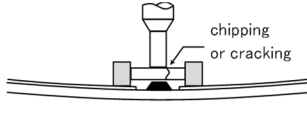
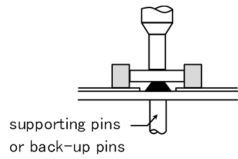
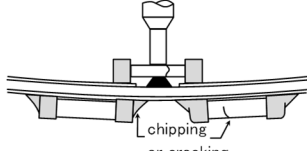
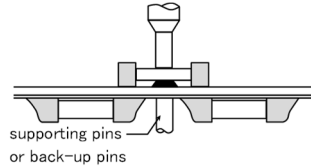
- When capacitors are mounted on PCB, excessive impact load shall not be imposed on them.
- Maintenance and inspection of mounting machines shall be conducted periodically.

◆ Selection of Adhesives

- When chips are attached on PCBs with adhesives prior to soldering, it may cause capacitor characteristics degradation unless the following factors are appropriately checked : size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, please contact us for further information.

◆ Adjustment of mounting machine

1. When the bottom dead center of a pick-up nozzle is too low, excessive force is imposed on capacitors and causes damages. To avoid this, the following points shall be considerable.
  - (1) The bottom dead center of the pick-up nozzle shall be adjusted to the surface level of PCB without the board deflection.
  - (2) The pressure of nozzle shall be adjusted between 1 and 3 N static loads.
  - (3) To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins shall be used on the other side of the PCB. The following diagrams show some typical examples of good and bad pick-up nozzle placement:

Item	Improper method	Proper method
Single-sided mounting		
Double-sided mounting		

Technical considerations

2. As the alignment pin is worn out, adjustment of the nozzle height can cause chipping or cracking of capacitors because of mechanical impact on the capacitors. To avoid this, the monitoring of the width between the alignment pins in the stopped position, maintenance, check and replacement of the pin shall be conducted periodically.

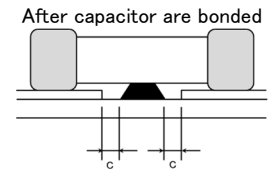
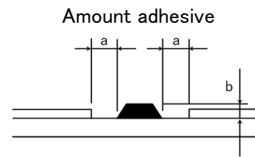
◆ Selection of Adhesives

Some adhesives may cause IR deterioration. The different shrinkage percentage of between the adhesive and the capacitors may result in stresses on the capacitors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect components. Therefore, the following precautions shall be noted in the application of adhesives.

- (1) Required adhesive characteristics
  - a. The adhesive shall be strong enough to hold parts on the board during the mounting & solder process.
  - b. The adhesive shall have sufficient strength at high temperatures.
  - c. The adhesive shall have good coating and thickness consistency.
  - d. The adhesive shall be used during its prescribed shelf life.
  - e. The adhesive shall harden rapidly.
  - f. The adhesive shall have corrosion resistance.
  - g. The adhesive shall have excellent insulation characteristics.
  - h. The adhesive shall have no emission of toxic gasses and no effect on the human body.
- (2) The recommended amount of adhesives is as follows:

[Recommended condition]

Figure	2012/3216 case sizes as examples
a	0.3mm min
b	100 to 120 μm
c	Adhesives shall not contact land



4. Soldering

◆ Selection of Flux

- Since flux may have a significant effect on the performance of capacitors, it is necessary to verify the following conditions prior to use;
- (1) Flux used shall be less than or equal to 0.1 wt% ( in Cl equivalent) of halogenated content. Flux having a strong acidity content shall not be applied.
  - (2) When shall capacitors are soldered on boards, the amount of flux applied shall be controlled at the optimum level.
  - (3) When water-soluble flux is used, special care shall be taken to properly clean the boards.

Precautions

◆ Soldering

Temperature, time, amount of solder, etc. shall be set in accordance with their recommended conditions. Sn-Zn solder paste can adversely affect MLCC reliability. Please contact us prior to usage of Sn-Zn solder.

Technical considerations

◆ Selection of Flux

- 1-1. When too much halogenated substance (Chlorine, etc.) content is used to activate flux, or highly acidic flux is used, it may lead to corrosion of terminal electrodes or degradation of insulation resistance on the surfaces of the capacitors.
- 1-2. Flux is used to increase solderability in wave soldering. However if too much flux is applied, a large amount of flux gas may be emitted and may adversely affect the solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.
- 1-3. Since the residue of water-soluble flux is easily dissolved in moisture in the air, the residues on the surfaces of capacitors in high humidity conditions may cause a degradation of insulation resistance and reliability of the capacitors. Therefore, the cleaning methods

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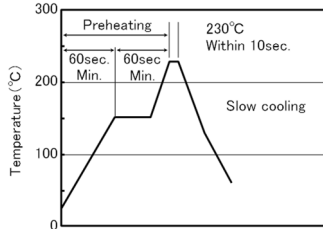
and the capability of the machines used shall also be considered carefully when water-soluble flux is used.

◆Soldering

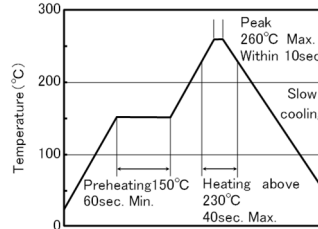
- Ceramic chip capacitors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling.
- Therefore, the soldering must be conducted with great care so as to prevent malfunction of the components due to excessive thermal shock.
- Preheating : Capacitors shall be preheated sufficiently, and the temperature difference between the capacitors and solder shall be within 130°C.
- Cooling : The temperature difference between the capacitors and cleaning process shall not be greater than 100°C.

[Reflow soldering]

【Recommended conditions for eutectic soldering】

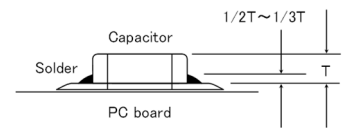


【Recommended condition for Pb-free soldering】



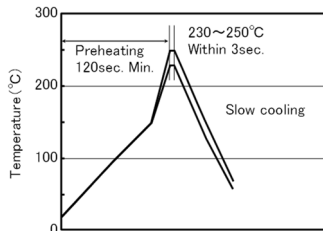
Caution

- ①The ideal condition is to have solder mass (fillet) controlled to 1/2 to 1/3 of the thickness of a capacitor.
- ②Because excessive dwell times can adversely affect solderability, soldering duration shall be kept as close to recommended times as possible. soldering for 2 times.

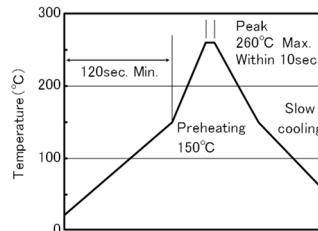


[Wave soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】

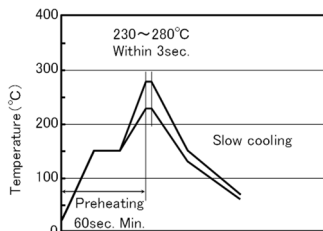


Caution

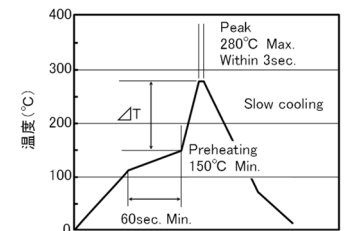
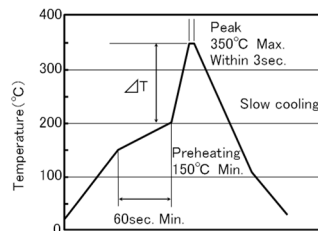
- ①Wave soldering must not be applied to capacitors designated as for reflow soldering only. soldering for 1 times.

[Hand soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】



	$\Delta T$
3216type or less	$\Delta T \leq 150^{\circ}\text{C}$

	$\Delta T$
3225type or more	$\Delta T \leq 130^{\circ}\text{C}$

Caution

- ①Use a 50W soldering iron with a maximum tip diameter of 1.0 mm.
- ②The soldering iron shall not directly touch capacitors. soldering for 1 times.

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5. Cleaning	
Precautions	<p>◆Cleaning conditions</p> <ol style="list-style-type: none"> <li>When PCBs are cleaned after capacitors mounting, please select the appropriate cleaning solution in accordance with the intended use of the cleaning. (e.g. to remove soldering flux or other materials from the production process.)</li> <li>Cleaning condition shall be determined after it is verified by using actual cleaning machine that the cleaning process does not affect capacitor's characteristics.</li> </ol>
Technical considerations	<ol style="list-style-type: none"> <li>The use of inappropriate cleaning solutions can cause foreign substances such as flux residue to adhere to capacitors or deteriorate their outer coating, resulting in a degradation of the capacitor's electrical properties (especially insulation resistance).</li> <li>Inappropriate cleaning conditions (insufficient or excessive cleaning) may adversely affect the performance of the capacitors. In the case of ultrasonic cleaning, too much power output can cause excessive vibration of PCBs which may lead to the cracking of capacitors or the soldered portion, or decrease the terminal electrodes' strength. Therefore, the following conditions shall be carefully checked:            Ultrasonic output : 20 W/l or less      Ultrasonic frequency : 40 kHz or less            Ultrasonic washing period : 5 min. or less</li> </ol>

6. Resin coating and mold	
Precautions	<ol style="list-style-type: none"> <li>With some type of resins, decomposition gas or chemical reaction vapor may remain inside the resin during the hardening period or while left under normal storage conditions resulting in the deterioration of the capacitor's performance.</li> <li>When a resin's hardening temperature is higher than capacitor's operating temperature, the stresses generated by the excessive heat may lead to damage or destruction of capacitors. The use of such resins, molding materials etc. is not recommended.</li> </ol>

7. Handling	
Precautions	<p>◆Splitting of PCB</p> <ol style="list-style-type: none"> <li>When PCBs are split after components mounting, care shall be taken so as not to give any stresses of deflection or twisting to the board.</li> <li>Board separation shall not be done manually, but by using the appropriate devices.</li> </ol> <p>◆Mechanical considerations</p> <p>Be careful not to subject capacitors to excessive mechanical shocks.</p> <ol style="list-style-type: none"> <li>If ceramic capacitors are dropped onto a floor or a hard surface, they shall not be used.</li> <li>Please be careful that the mounted components do not come in contact with or bump against other boards or components.</li> </ol>

8. Storage conditions	
Precautions	<p>◆Storage</p> <ol style="list-style-type: none"> <li>To maintain the solderability of terminal electrodes and to keep packaging materials in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible.           <ul style="list-style-type: none"> <li>Recommended conditions                Ambient temperature : Below 30°C      Humidity : Below 70% RH</li> </ul>           The ambient temperature must be kept below 40°C. Even under ideal storage conditions, solderability of capacitor is deteriorated as time passes, so capacitors shall be used within 6 months from the time of delivery.           <ul style="list-style-type: none"> <li>Ceramic chip capacitors shall be kept where no chlorine or sulfur exists in the air.</li> </ul> </li> <li>The capacitance values of high dielectric constant capacitors will gradually decrease with the passage of time, so care shall be taken to design circuits. Even if capacitance value decreases as time passes, it will get back to the initial value by a heat treatment at 150°C for 1hour.</li> </ol>
Technical considerations	<p>If capacitors are stored in a high temperature and humidity environment, it might rapidly cause poor solderability due to terminal oxidation and quality loss of taping/packaging materials. For this reason, capacitors shall be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the capacitors.</p>

※RCR-2335B (Safety Application Guide for fixed ceramic capacitors for use in electronic equipment) is published by JEITA.

Please check the guide regarding precautions for deflection test, soldering by spot heat, and so on.